

The New and Complete Belle II DEPFET Pixel Detector: Commissioning and Previous Operational Experience

Jannes Schmitz on behalf of the PXD collaboration

Belle II Germany Meeting

Bonn, September 9, 2025



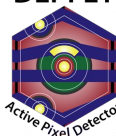
bmb+f - Förderschwerpunkt

Elementarteilchenphysik

Großgeräte der physikalischen
Grundlagenforschung

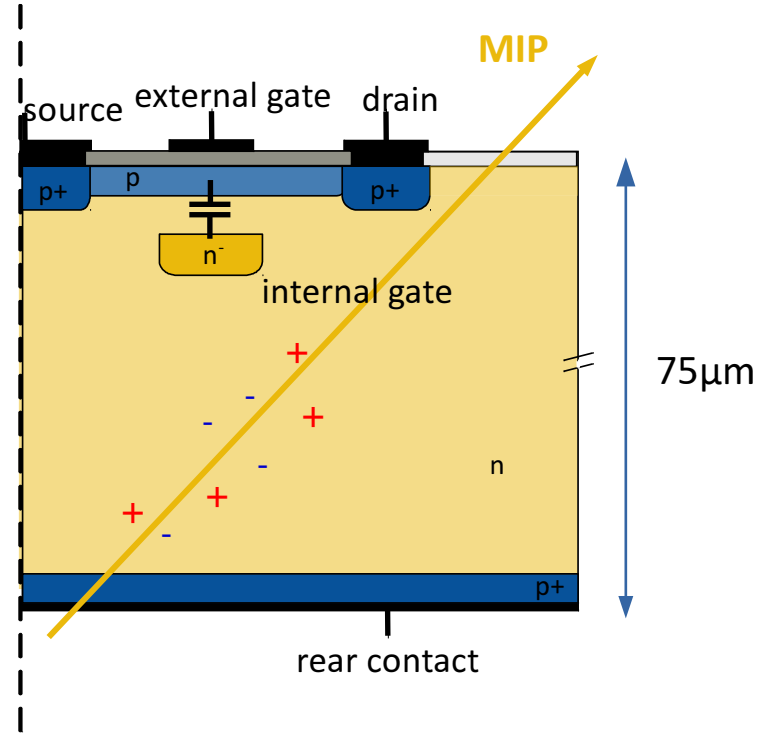


DEPFET



DEPFET PIXEL PRINCIPLE

- **DE**pleted **P**-channel **F**ield **E**ffect **T**ransistor (DEPFET)
- MOSFET on top of fully depleted silicon bulk
- Fast charge collection ($\sim$ ns) in internal gate
- Charge in int. gate modulates drain-source current
- Internal amplification
- High signal-to noise ratio $g_q = \frac{\partial I_D}{\partial q} \approx 750 \frac{pA}{e^-}$
- Periodic clearing required



DEPFET PIXEL OPERATION

- Matrix readout steered by gate and clear voltages

CHARGE COLLECTION

gate off, clear off:

- Charges drift to internal gate
- No drain current

SAMPLING

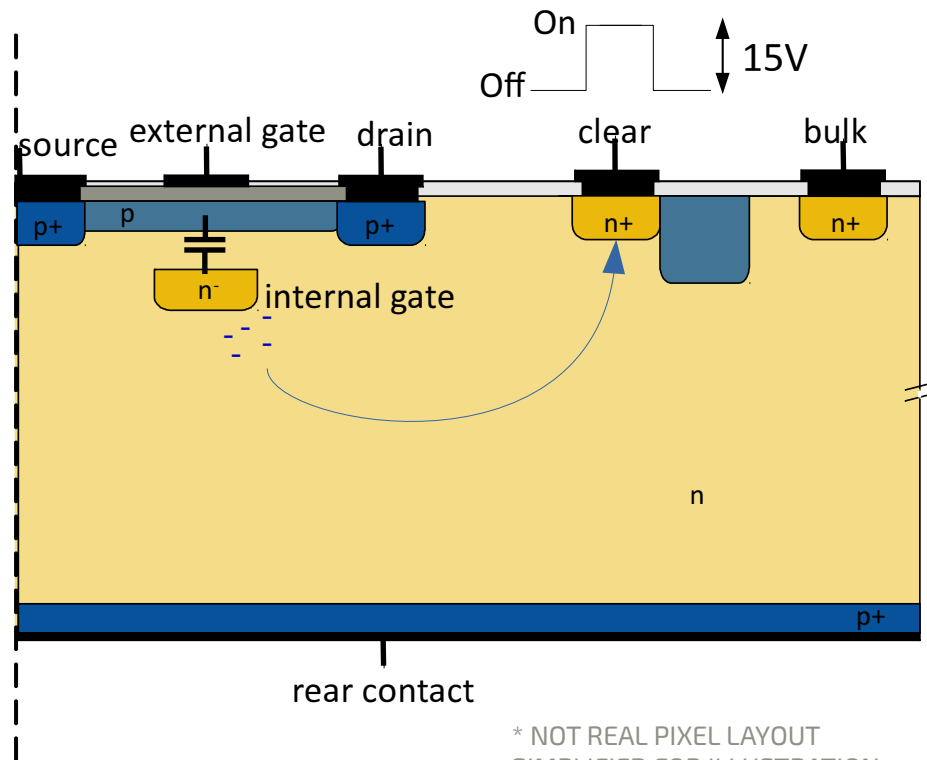
gate on, clear off:

- Readout of stable drain current

CLEARING

gate on, clear on:

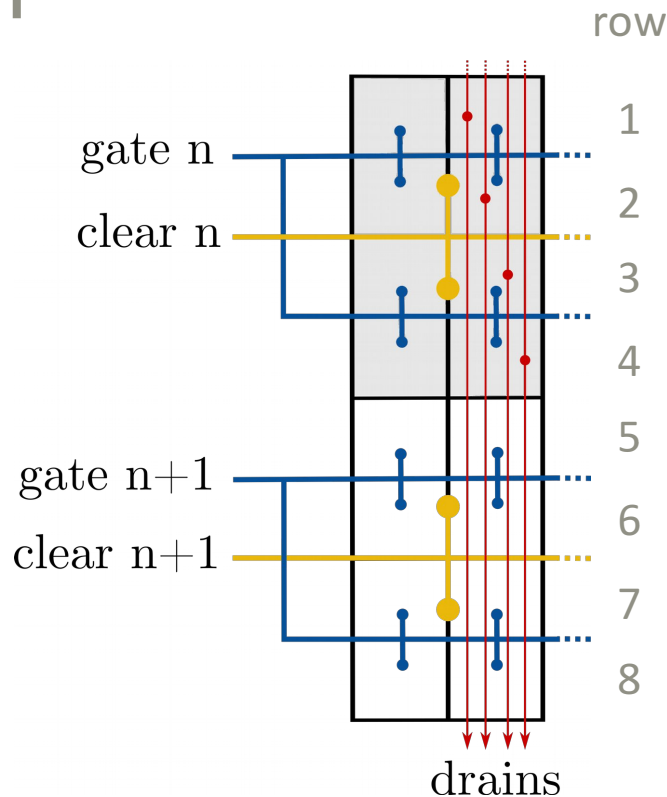
- Charges drift from internal gate to clear implant

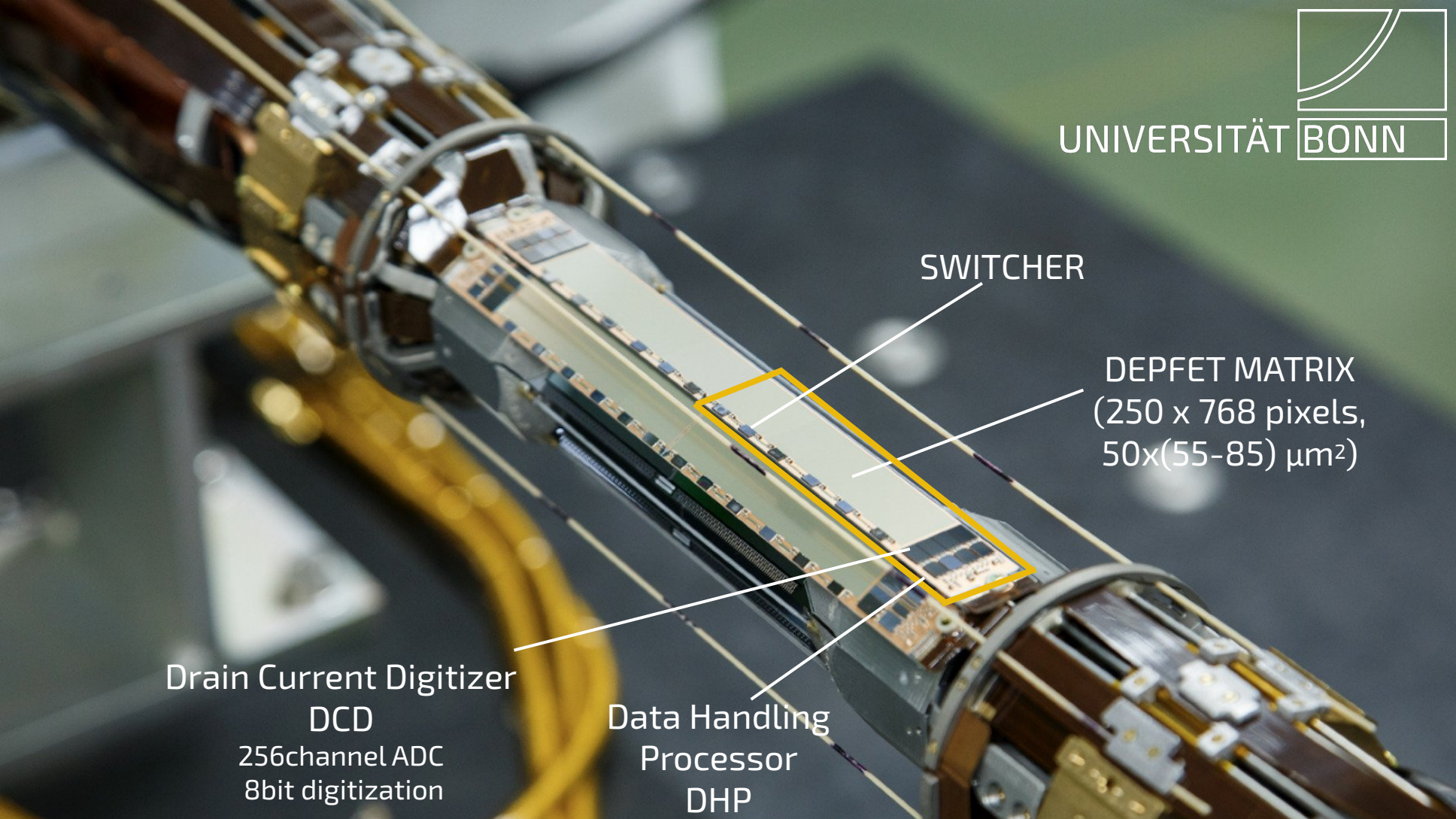


* NOT REAL PIXEL LAYOUT
SIMPLIFIED FOR ILLUSTRATION

DEPFET PIXEL READOUT

- Rolling shutter readout mode with four active matrix rows at once
 - low power consumption
 - Control signals are shared among pixels
 - 20 μ s integration time (2x beam revolution)
- Modulated drain current processed via drain lines
- Different ASICs for row control and signal processing





SWITCHER

DEPFET MATRIX
(250 x 768 pixels,
50x(55-85) μm^2)

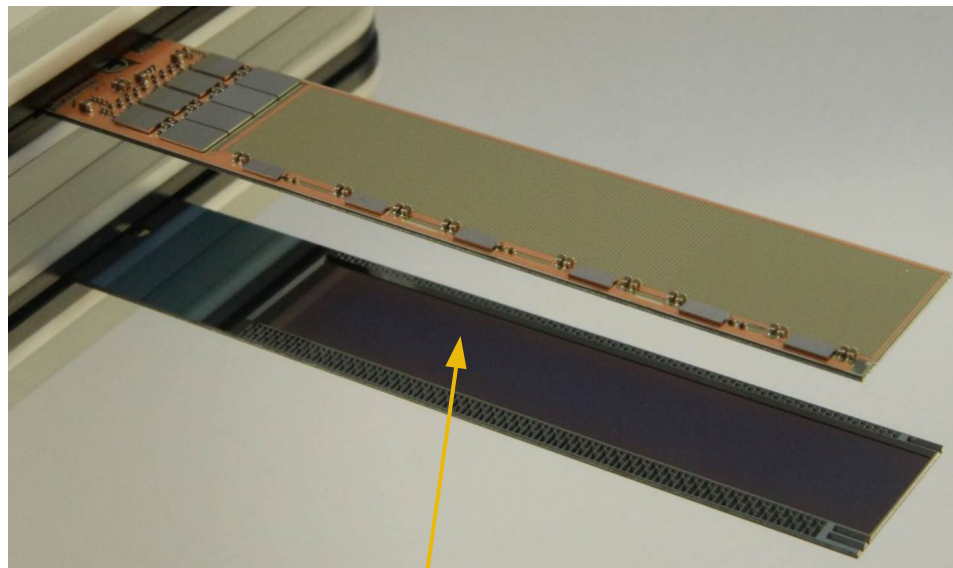
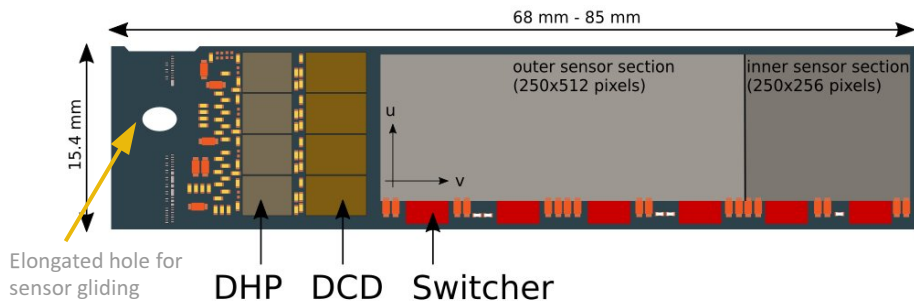
Data Handling
Processor
DHP

Drain Current Digitizer
DCD
256channel ADC
8bit digitization

THE PIXEL VERTEX DETECTOR (PXD) MODULE

PROPERTIES

- Self-supporting **all-silicon** design
 - 450-525 μm thick support frame
 - Active region thinned to 75 μm
 - small total material budget $\sim 0.21\% X_0$
- Pixel size 50 x (55-85) μm^2

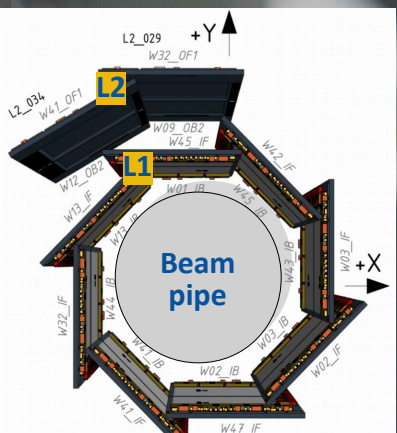


Thinned backside at active sensor area



BONN

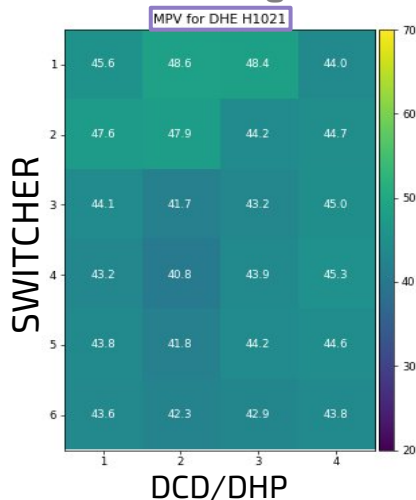
PREVIOUS OPERATIONAL EXPERIENCE



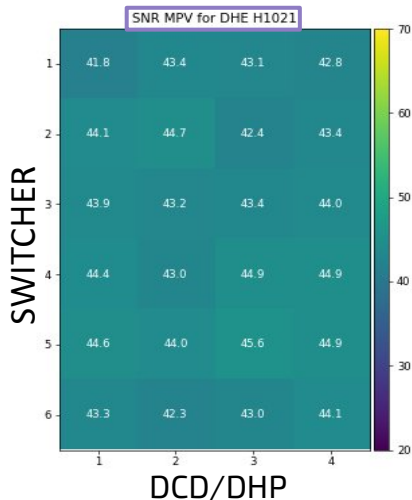
PXD1 PERFORMANCE

- Homogeneous signal and noise response across module matrix
- Noise performance < 1 ADU ($\sim 200e^-$) at SNR of ~ 30 -50 (noise slightly increasing with DCD irradiation)
- Stable throughout 2019-2022

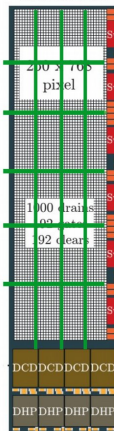
cluster charge MPV



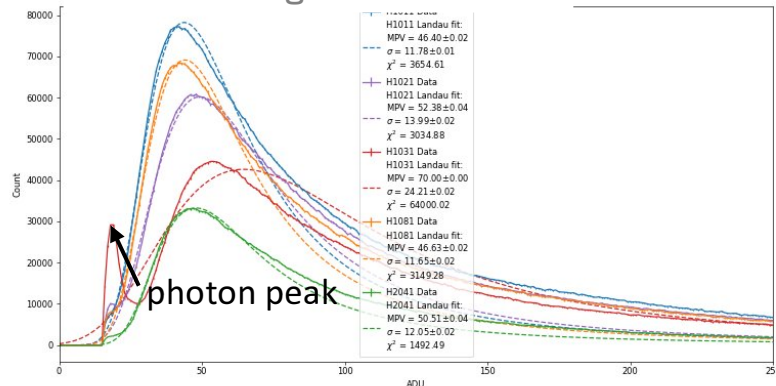
SNR MPV



half ladder

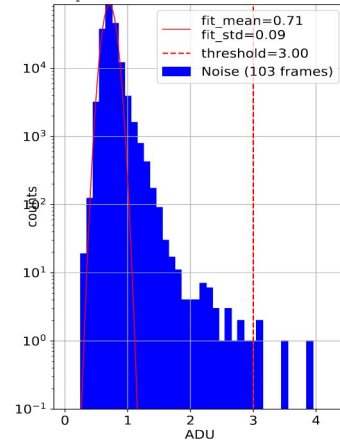


cluster charge distribution



multi pixel cluster ADU

pedestal noise



PXD1 EFFICIENCY

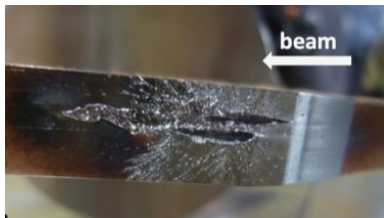
DI-MUON HIT EFFICIENCY

- ~99% in fiducial regions
- ~96% in physics region

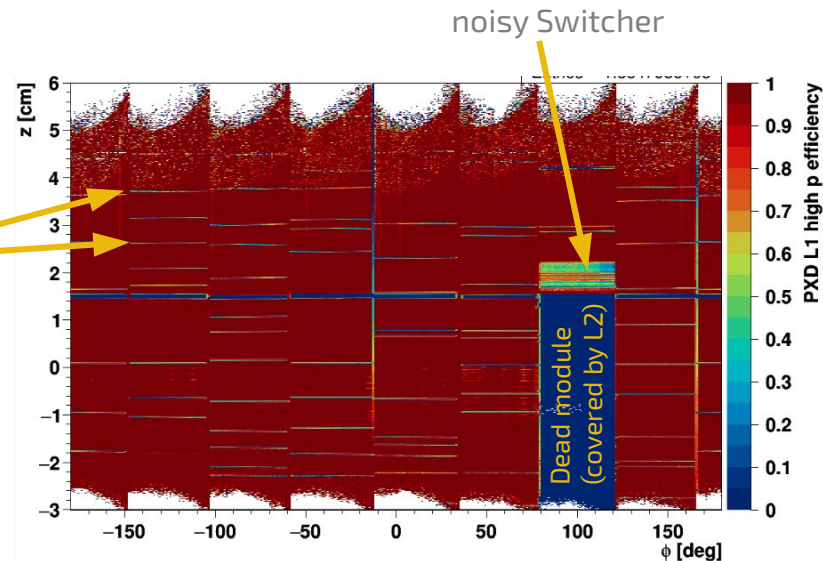
BEAM LOSS EVENTS

- Radiation bursts to PXD up to 3Gy in 40 μ s
- Permanent Switcher damage after beam incidents
 - Inefficient/dead readout rows
 - ~3% drop in efficiency
- Possible mitigation:
 - Accelerator : - earlier detection
- faster beam dump
 - PXD: - faster emergency shutdown

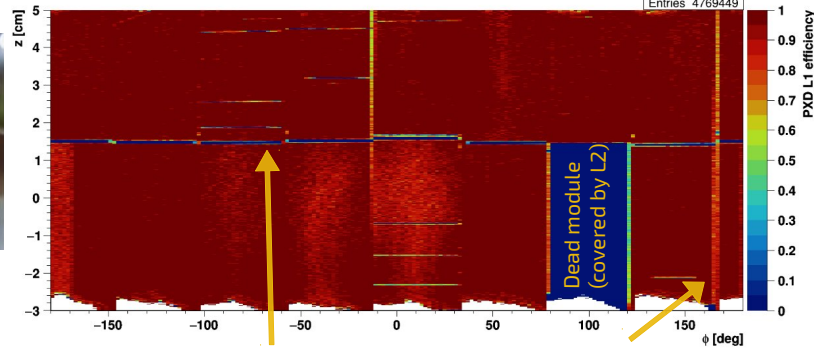
inefficient/dead
readout channels



Lost beam hitting collimator
→ high inst. radiation



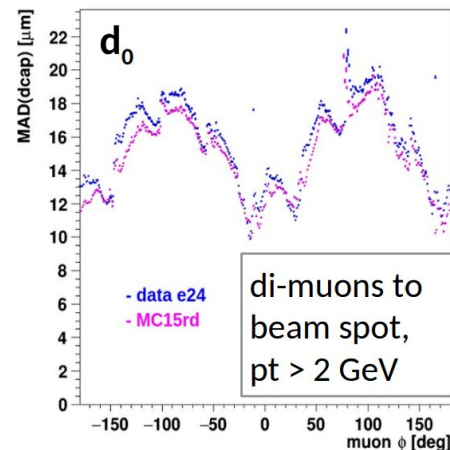
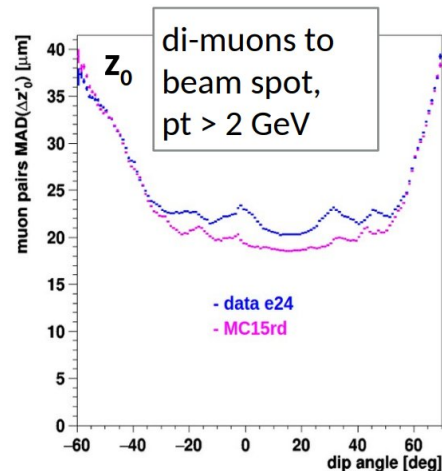
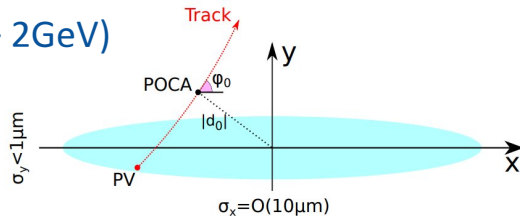
2019 state



Glue gaps ~0.8mm Half-shell gaps

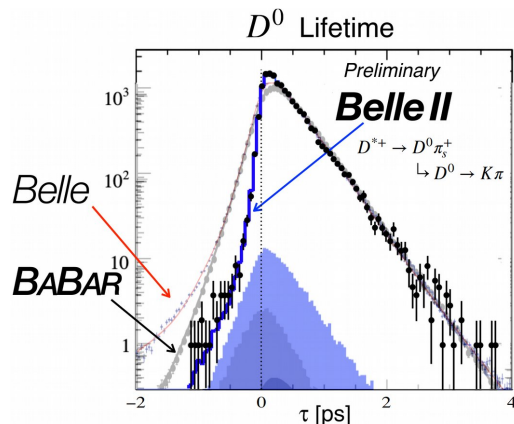
IMPACT PARAMETER RESOLUTION

- Di-muon events ($p_t > 2\text{ GeV}$)
 - z_0 : 20 – 40 μm
 - d_0 : 10 – 22 μm
- MC describes data
 - MC slightly too optimistic ($\Delta z_0 \approx 3\mu\text{m}$, $\Delta d_0 \approx 1.5\mu\text{m}$)
- $\sim 1.5 - 2$ times better than Belle



D⁰ LIFETIME RESOLUTION

- Impact of better vertex detector
 - Belle II D⁰ lifetime resolution ~ 2 times better



Belle II lifetime measurements with high PXD impact:

D_s^+ : [arXiv:2306.00365](https://arxiv.org/abs/2306.00365) → PRL
 B^0 : PRD 107, L091102 (2023)
 Ω_c^+ : PRD 107, L031103 (2023)
 Λ_c^+ : PRL 130, 071802 (2023)
 D^0/D^+ : PRL 127, 211801 (2021)

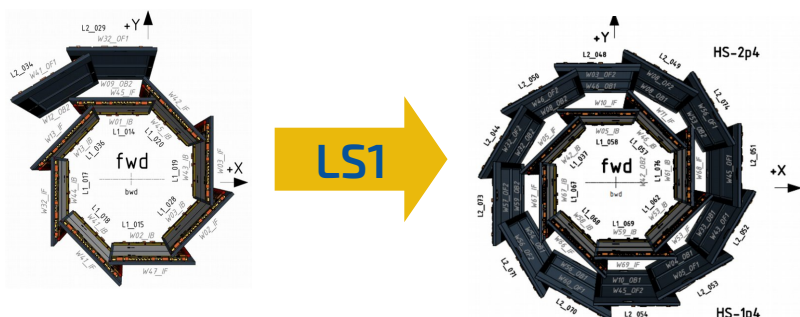
PXD2

COMMISSIONING AND FIRST COSMIC DATA



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FULLY POPULATED 2-LAYER PXD2



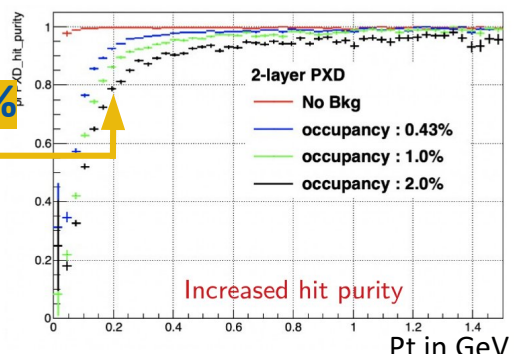
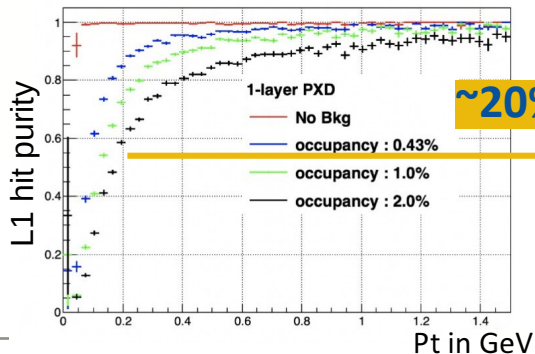
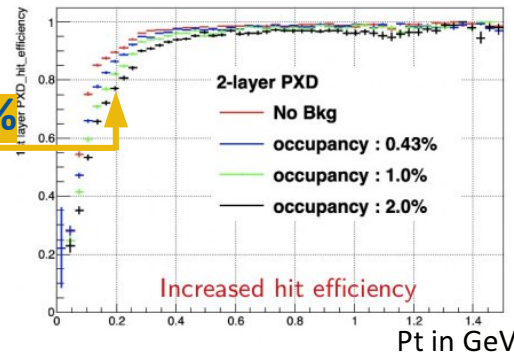
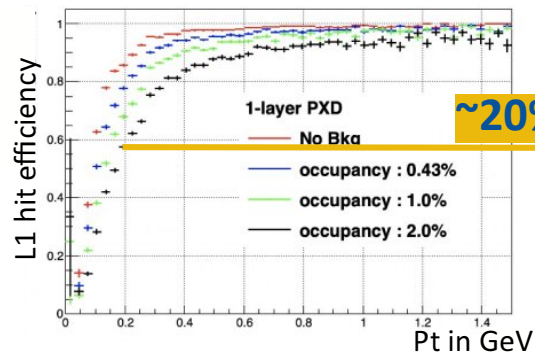
BENEFIT OF 2ND PXD LAYER

- Modest improvement of impact parameters (L1 highest impact)
- Higher probability to select correct PXD hits in 1st PXD layer at higher background levels
- Fraction of MC hits found in reconstructed track

$$\text{hit efficiency} = \frac{N_{\text{mc_hits_in_reco_track}}}{N_{\text{hits, mc_track}}}$$

- Fraction of MC hits in reconstructed track hits (how much background was picked up?)

$$\text{hit purity} = \frac{N_{\text{mc_hits_in_reco_track}}}{N_{\text{hits, reco_track}}}$$





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PXD2 COMMISSIONING DESY

HALF-SHELL COMMISSIONING (DESY, HAMBURG)

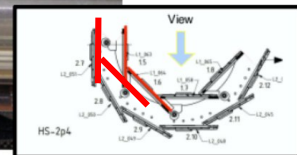
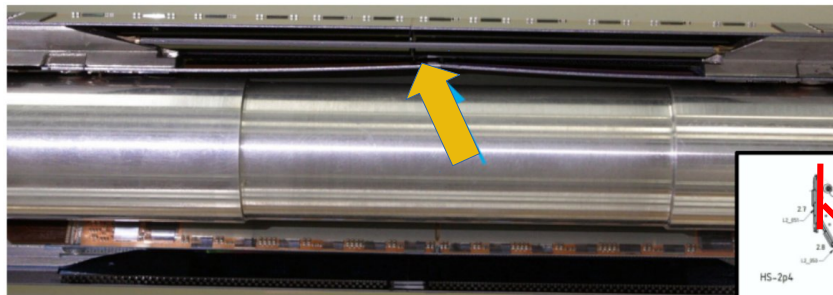
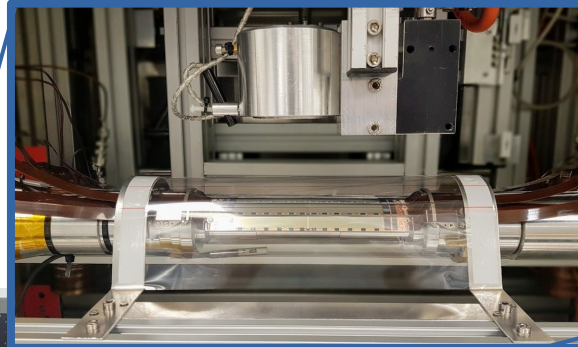
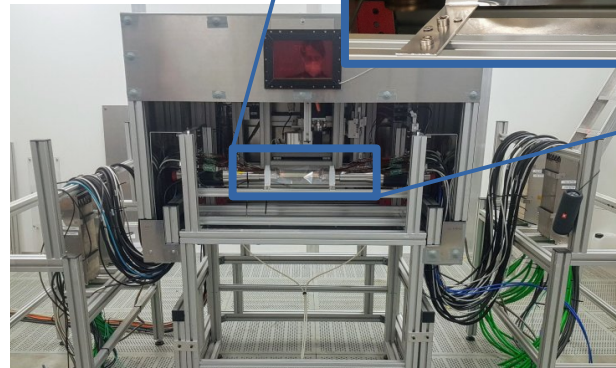
- Pre-commissioning with full services, CO₂ and N₂ cooling
- Half-shell mounted on aluminum dummy beampipe
- Movable ⁹⁰Sr for signal response tests
- 1st half-shell damaged during long-term operation

PROBLEMS FOUND

- Non optimal PXD ladder gliding
 - Kink in 2 L1 ladders, Repair & Reassembly
 - Adjusted screw torque to improve gliding

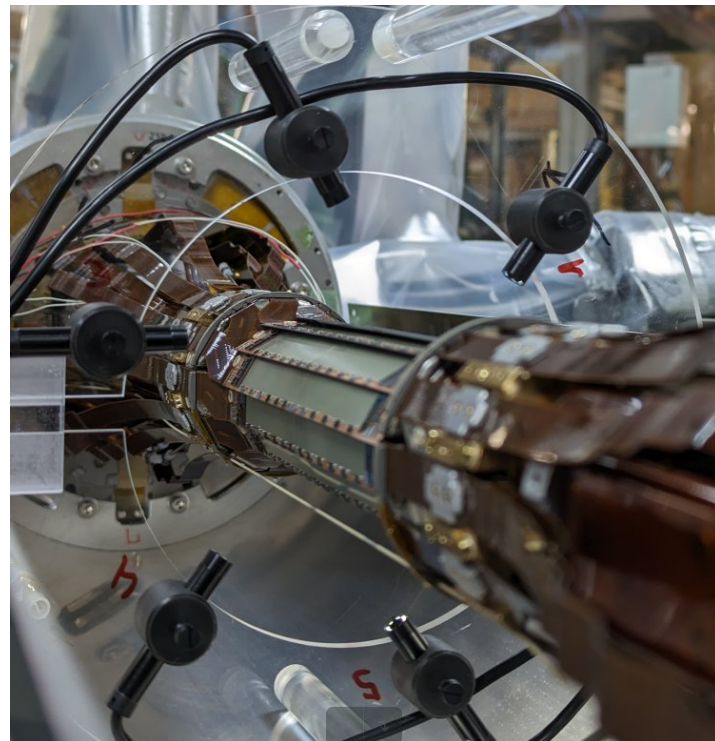
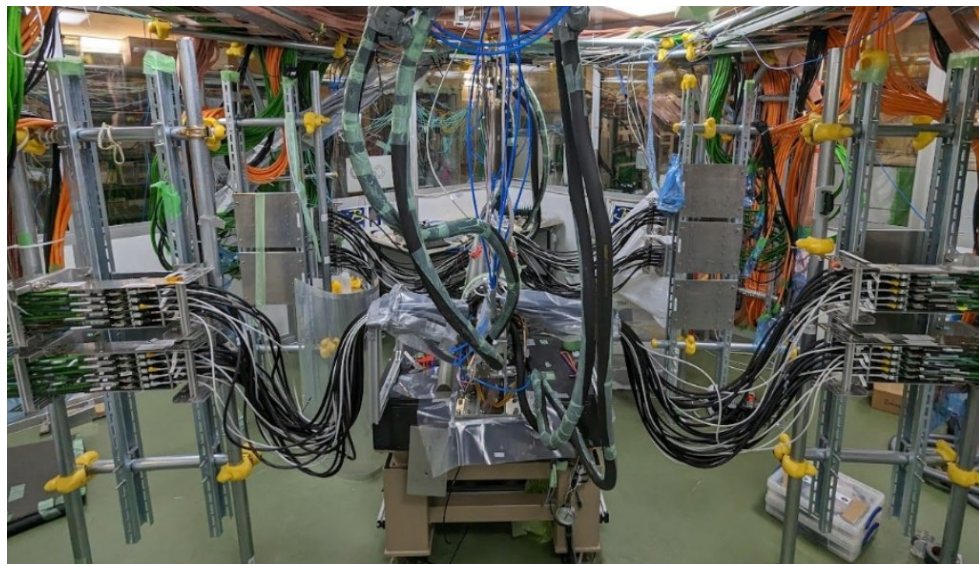
DEDICATED ENDURANCE STUDIES

- >90k cycles with sagitta >1mm
 - Ladders quite robust against bowing
- Elevated temp + bowing might open glue joint



PXD2 STANDALONE TESTING

- Full optical & environmental monitoring in dry volume
- Step by step module operation with cooling adjustments
 - Successive full detector operation
 - Significant bending ($\sim 1\text{mm}$) in 2 outer ladders

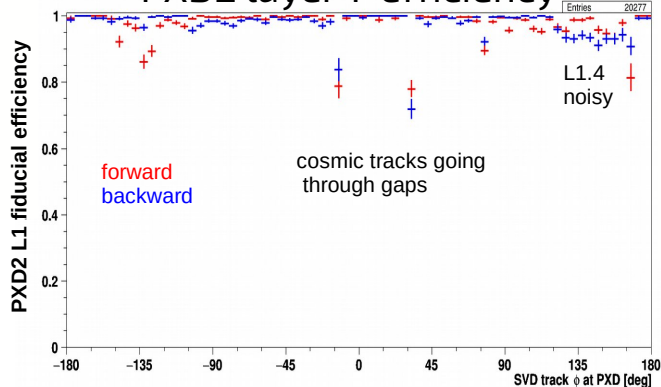


FIRST PXD2 COSMIC DATA SEPTEMBER23 (NO B-FIELD)

EFFICIENCY

- Extrapolated SVD tracks
- Reaching > 98% in most regions
- Eff. Drops due to
 - Gaps for cosmes
 - Masked noisy pixels (esp. L2.12bwd)
 → further module tuning ongoing

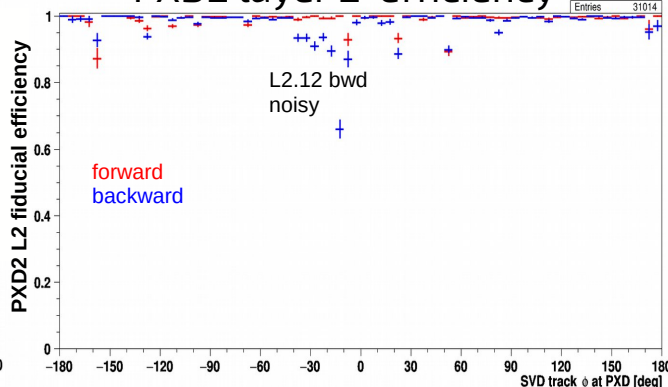
PXD2 layer 1 efficiency



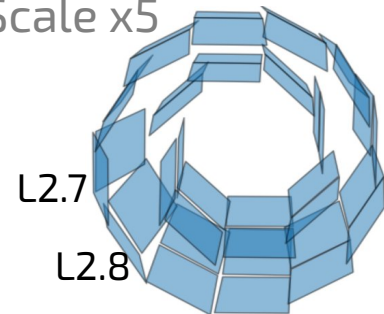
ALIGNMENT

- Extrapolated CDC tracks
- Alignment done per module
 - 6 rigid body, 7 deformation parameters
- Ladder bowing visible
 - Up to ~1mm for L2.7/L2.8

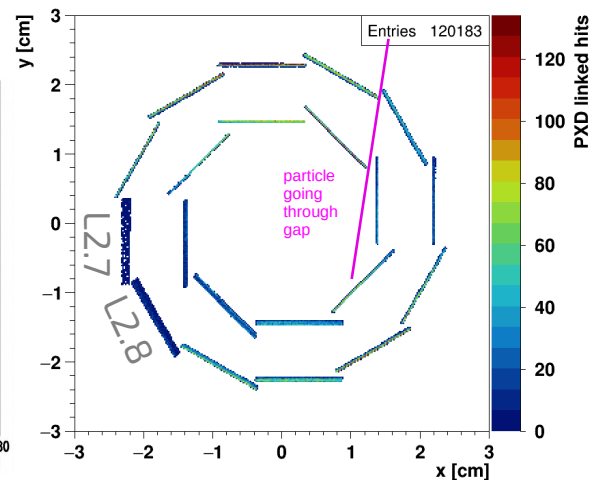
PXD2 layer 2 efficiency



Scale x5



xy-projection of spacial cosmic hits after alignment

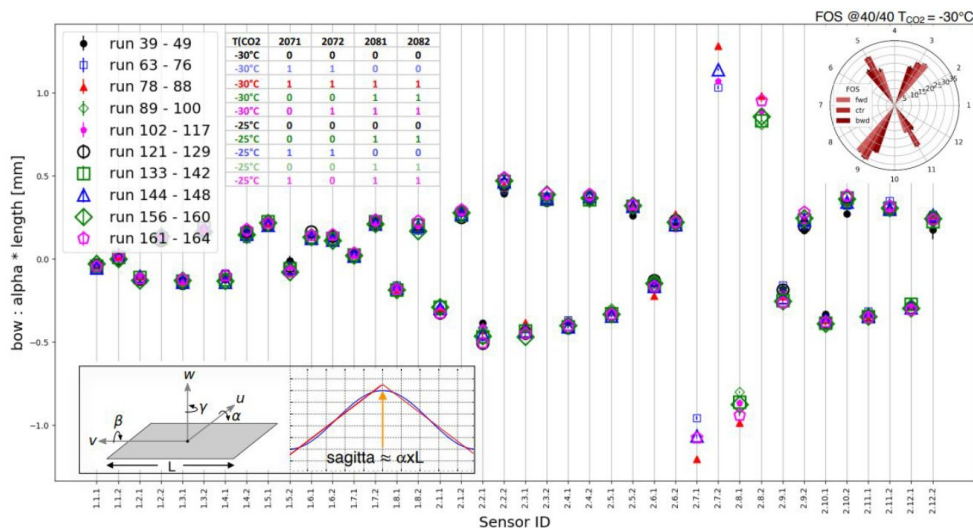


thickness indicates ladder bowing 15

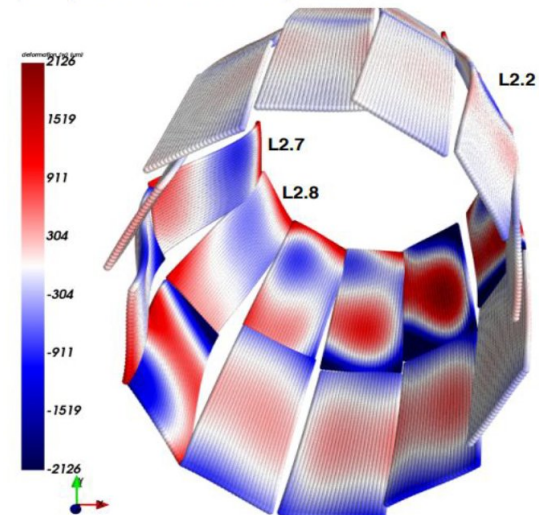
PXD2 BENDING COSMIC STUDIES

ALIGNMENT STUDIES WITH DIFFERENT COOLING CONFIGURATIONS

- Confirmed $\sim 1\text{mm}$ sagitta for two ladders (less than tested in endurance tests)
- Decided to keep both ladders off during operation start



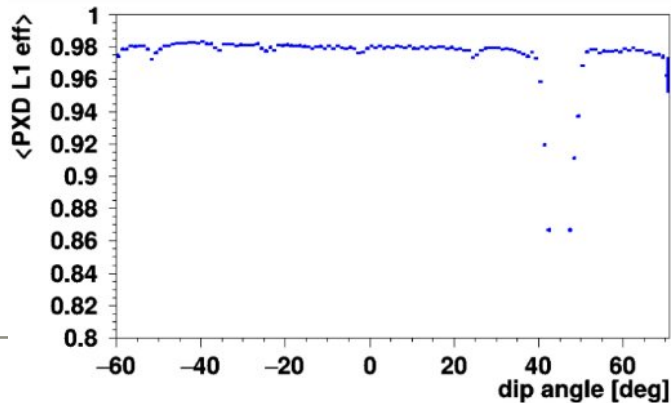
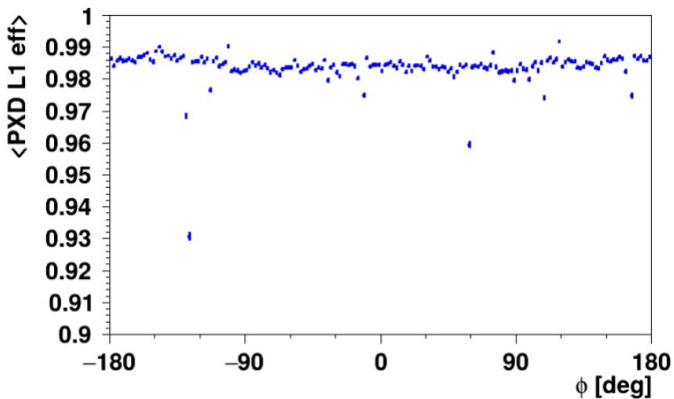
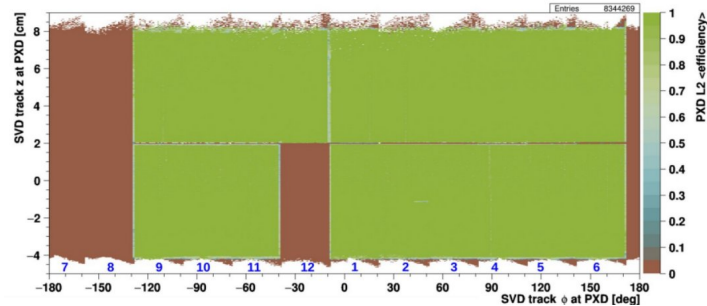
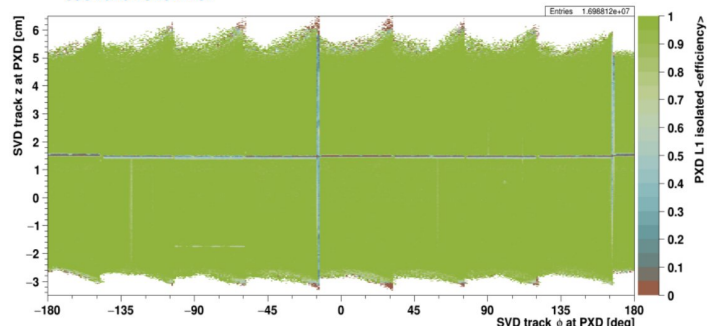
Here: All misalignment parameters in payloads multiplied by 10. Sensor 3D surface plotted point by point (+ color for w-coordinate)



OPERATION IN 2024AB

- Running with 35/40 modules
 - 4 Module off because of bowing
 - 1 Module off because of noise
- L1 and L2 efficiency > 98% in fiducial region
- Smooth Operation, temperatures high, but within limits

e30 runs 2343-2407



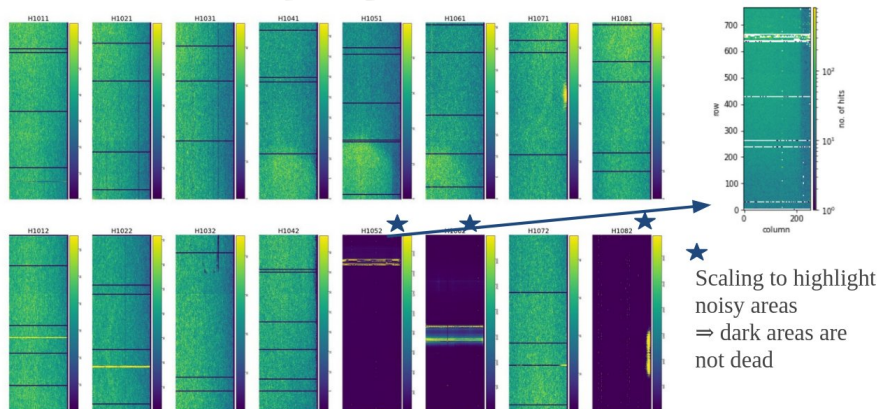
dip angle = $90 - \theta$

PXD2 PERFORMANCE AFTER SBLS

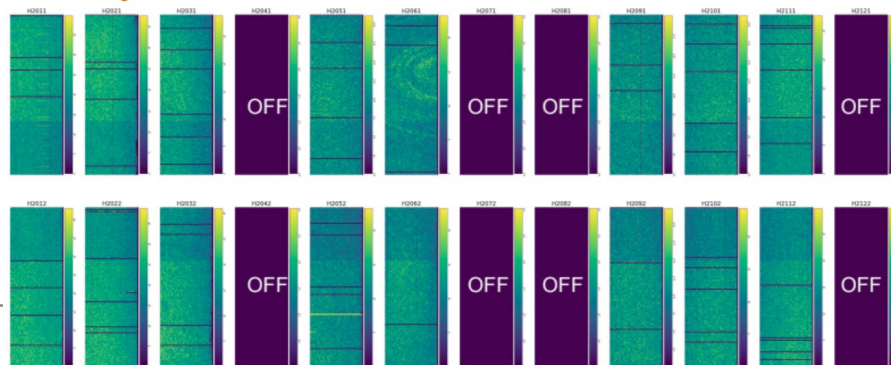
AFTERMATH

- Two sudden beam losses in April/May 2024
→ Dead gates and noisy Switchers
→ Increased Switcher currents
- Lost ~2% of active pixels
- Decided to turn off another 3 modules to compensate temperature rise from currents
- PXD2 completely turned off to prevent further damage after 2nd SBL

LAYER 1



LAYER 2



BEAM LOSS EVENTS

CAUSE

- Vacuum leak sealant “VACSEAL” found to be strong candidate for causing SBL events

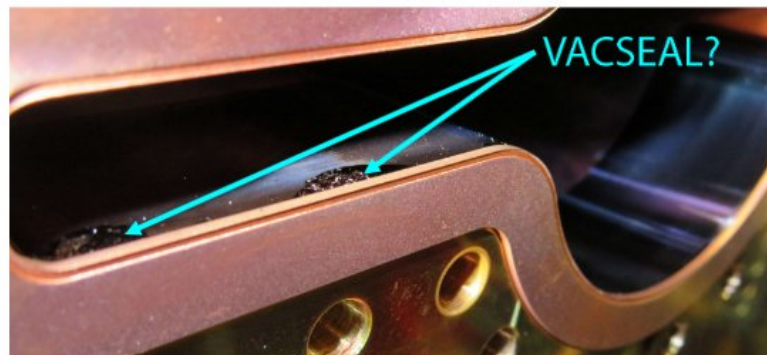
IMPACT OF VACSEAL REMOVAL

- One bellows chamber exchanged on 6th Nov. 2024
- Before (Oct 9th – Nov 6th) : 0.141 SBL / beam dose(1/Ah)
- After (Nov 6th – Dec 27th) : 0.043 SBL / beam dose (1/Ah)
- No SBLs with pressure burst in this section after replacement

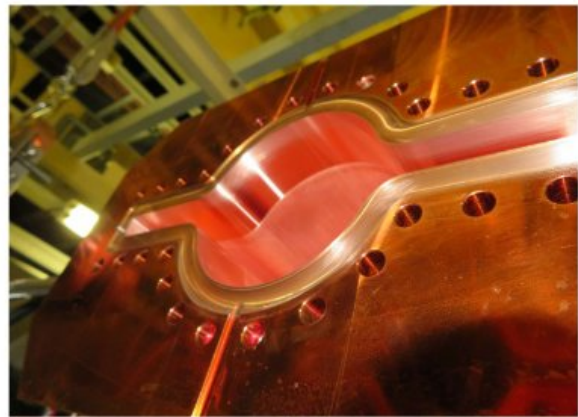
OUTLOOK

- Cleaning and VACSEAL removal in pipes and bellows done for most sections during 2025 shutdown
- Likely not the only source, but one main contributor
 - Need to observe SBL numbers in next run
- Lot of ongoing work on early SBL detection & fast PXD shutdown

Before removal



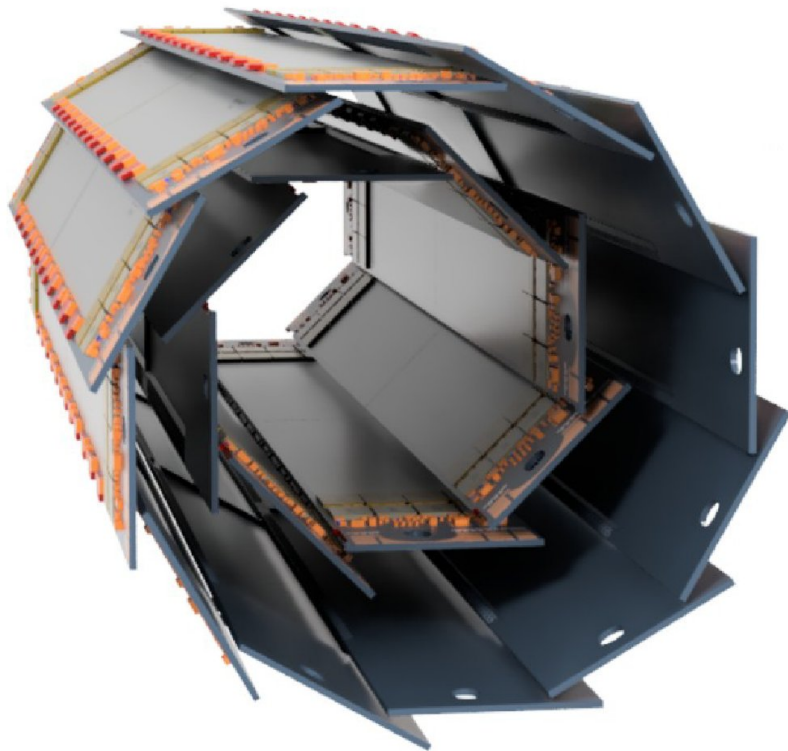
After removal



SUMMARY

PXD1 (2019-2022)

- 4 years successful operation with single layer
- Overall efficiency $\sim 96\%$
- 2x improvement of D^0 lifetime resolution
(compared to previous experiment)
- Challenges: beam backgrounds and beam losses



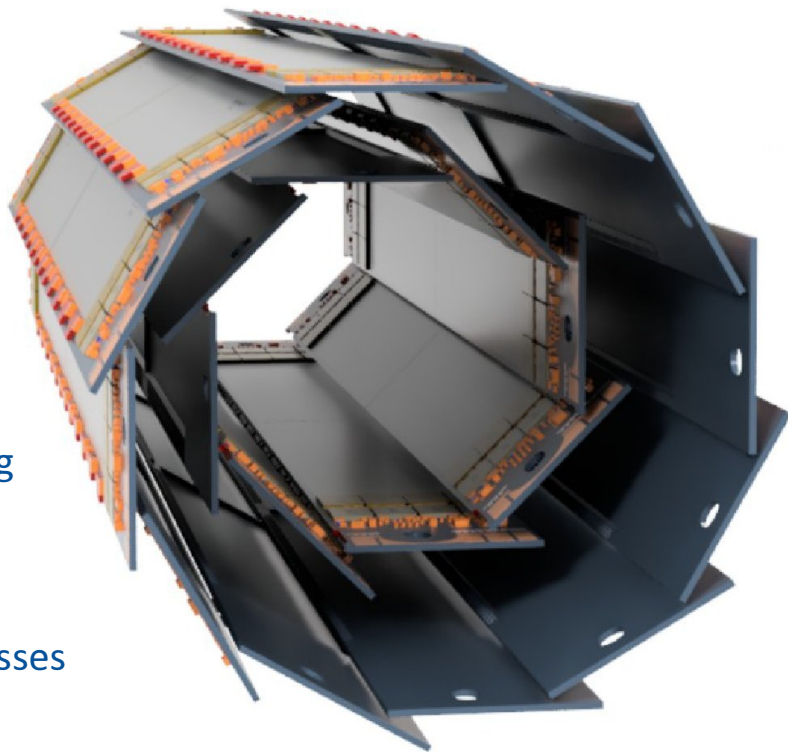
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PXD2 (SINCE 2023)

- All 40 modules operable after successful commissioning
- L1 and L2 efficiency $> 98\%$ in fiducial region
- Challenges : - 2 ladders show significant bending
- 2% dead pixel and increased operational temperatures caused by sudden beam losses



SUMMARY

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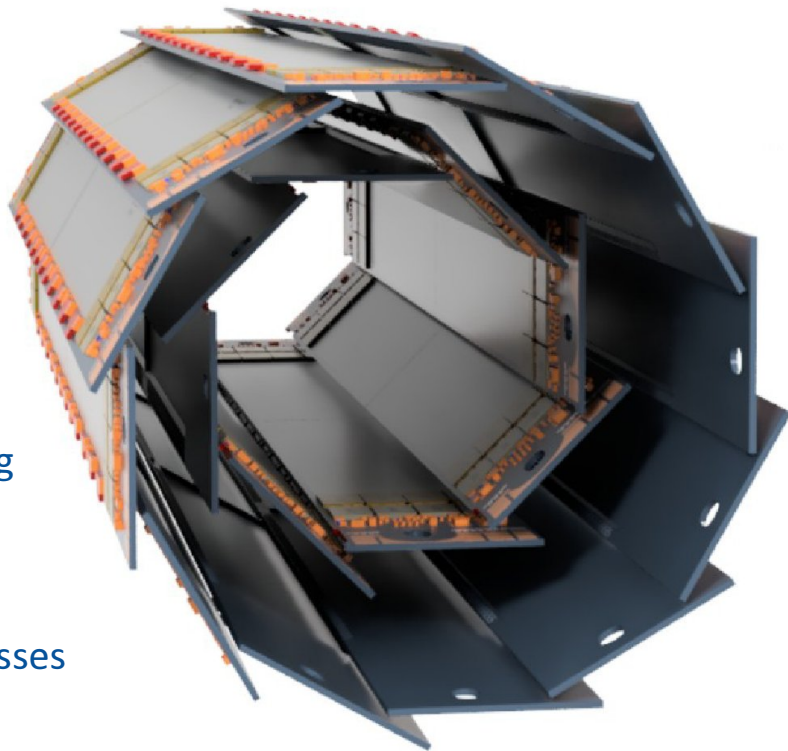
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OUTLOOK

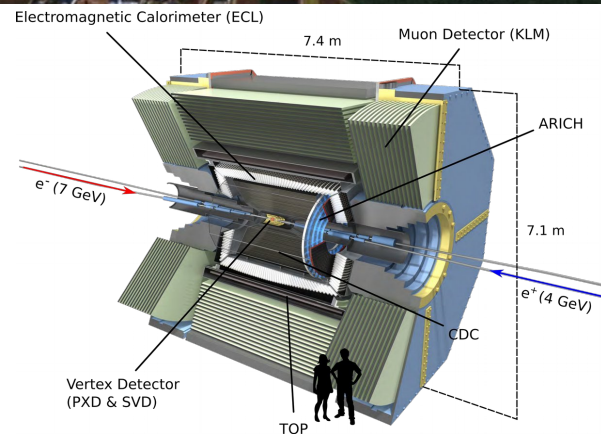
- PXD2 turned off for now
→ Work on optimized beam operation, SBL prevention/detection and fast shutdown ongoing
- PXD2 especially needed for later runs with high luminosity and higher background



BACKUP

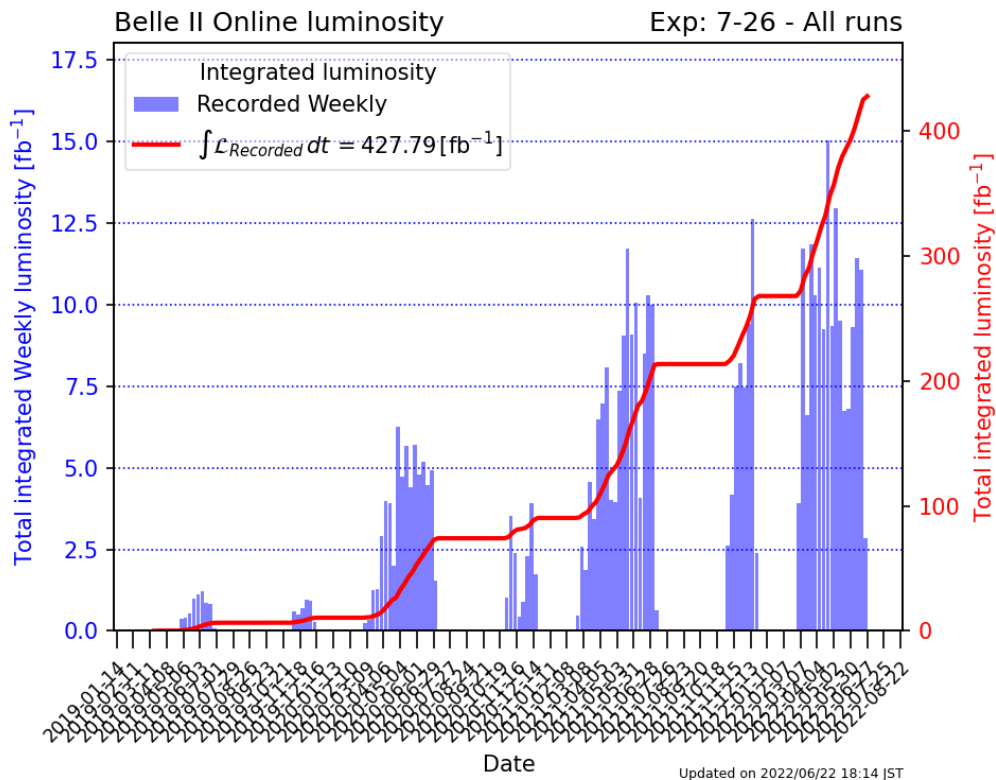
SUPERKEKB ACCELERATOR & BELLE II DETECTOR

- Asymmetric e^+e^- collider in Tsukuba , Japan
- $E_{\text{CM}} = M_{Y(4S)} \approx 10.58 \text{ GeV} \rightarrow \text{“B factory”}$
- Physics data-taking March 2019 – July 2022
- Recorded a total physics data set of $L_{\text{int}} \approx 424 \text{ fb}^{-1}$
- $L_{\text{peak}} = 4.7 \times 10^{34} \text{ cm}^{-2}\text{s}^{-1}$ (June 2022)
- Ongoing long shutdown (LS1) since July 2022
 - ~1.5 years for accelerator and detector improvements



TOTAL INTEGRATED LUMINOSITY FOR GOOD RUNS

- Total L_{int} : 424 fb^{-1}
- Total L_{int} at Y(4S) : 363 fb^{-1}
- Total L_{int} below Y(4S) : 42 fb^{-1}
- Total L_{int} above Y(4S) : 19 fb^{-1}



THE VERTEX DETECTOR (VXD)

SILICON VERTEX DETECTOR (SVD)

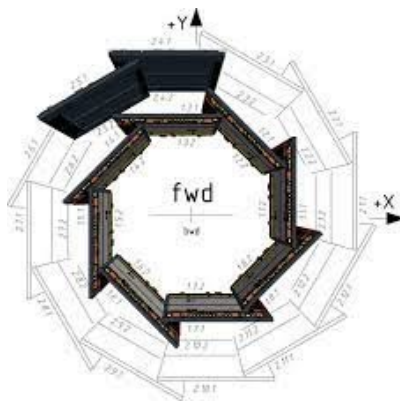
- 4 layers double-sided silicon strips
- $R \leq 140\text{mm}$

PIXEL VERTEX DETECTOR (PXD)

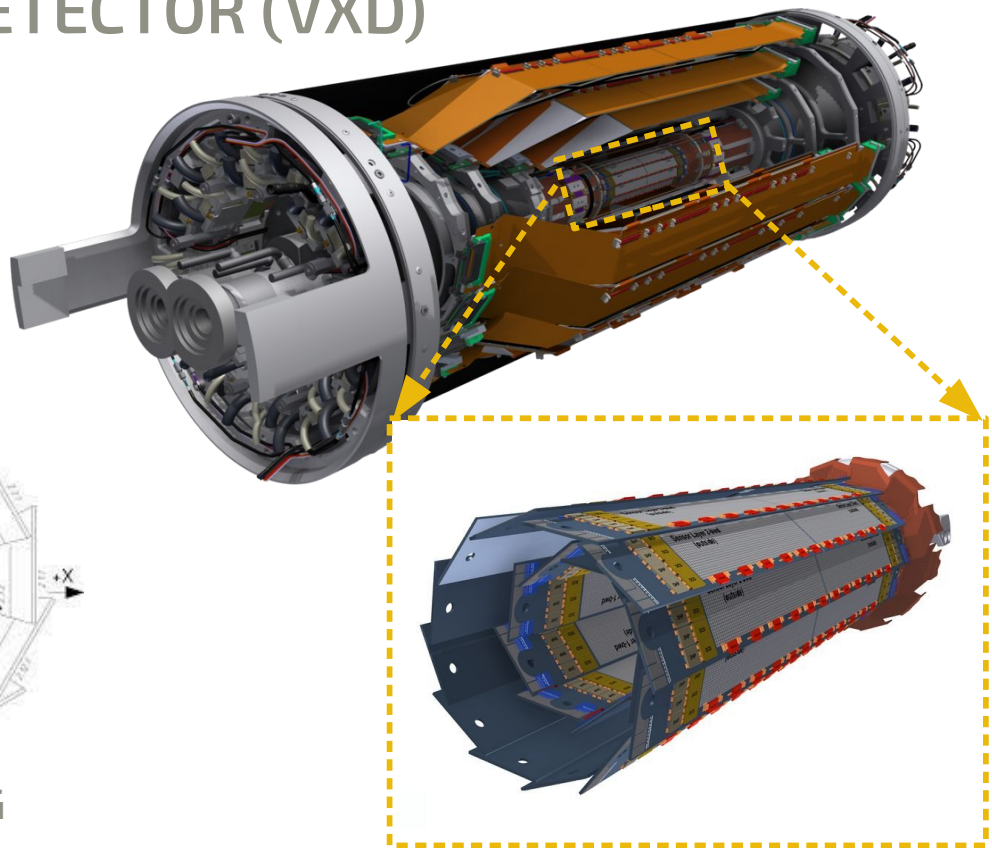
- 2-layer DEPFET
PXD1 2019-2022 incomplete
PXD2 from 2023 full 2-layer
- $r_1 = 14\text{mm}$, $r_2 = 22\text{ mm}$

ACCEPTANCE

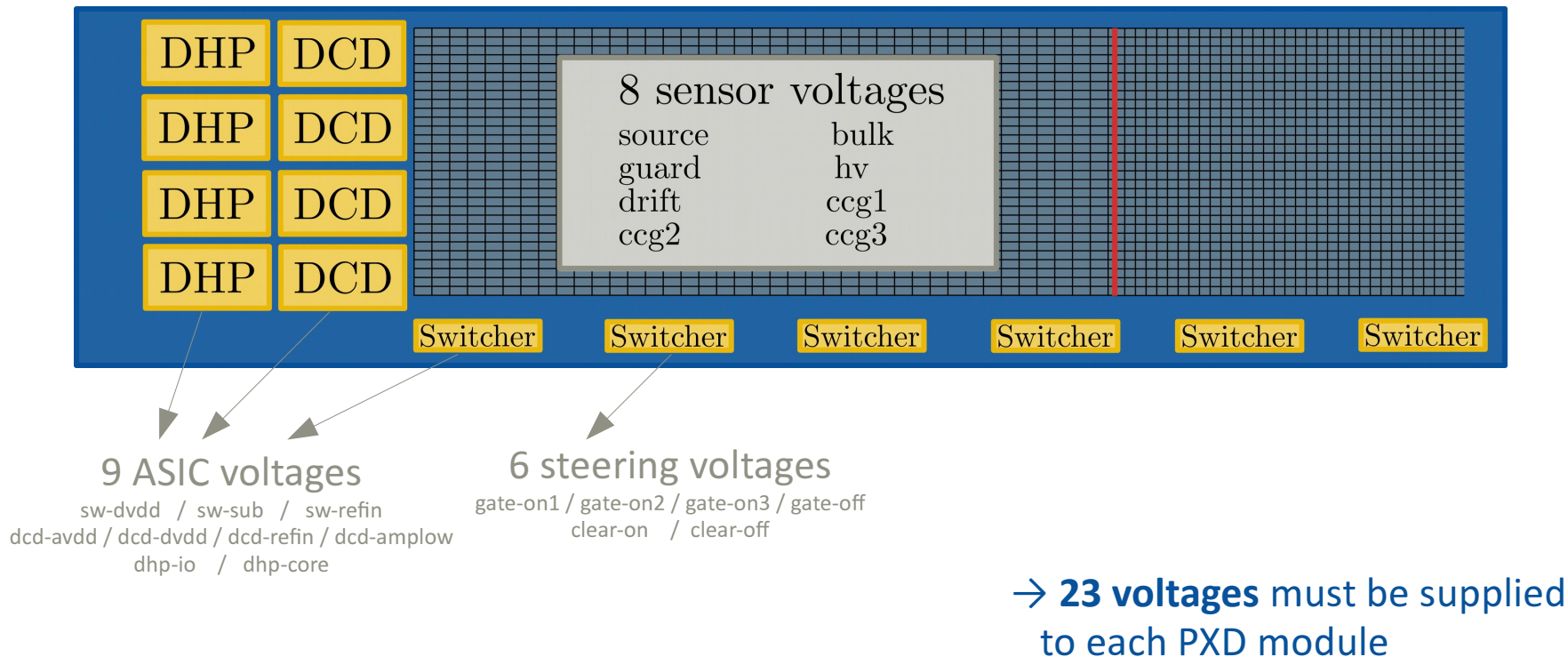
- $17^\circ < \Theta < 150^\circ$
- $p_t \geq 40\text{ MeV}$



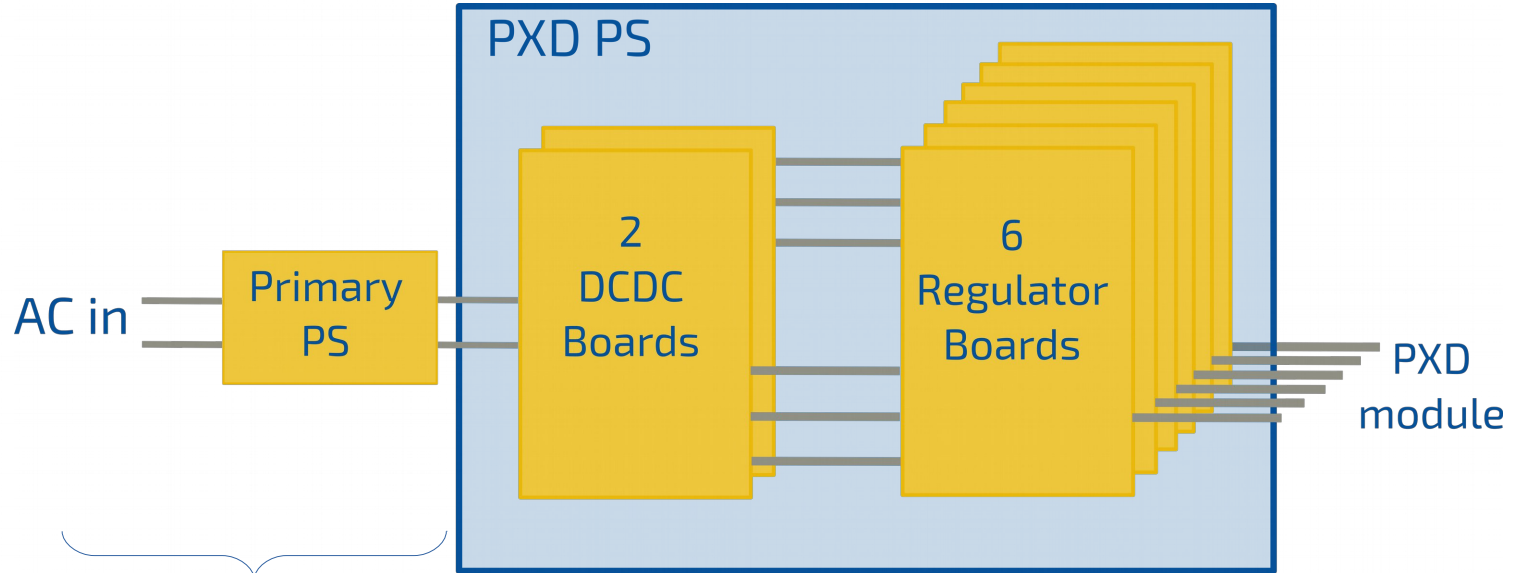
PXD1 CONFIG



PXD POWER REQUIREMENTS



PS SYSTEM ARCHITECTURE



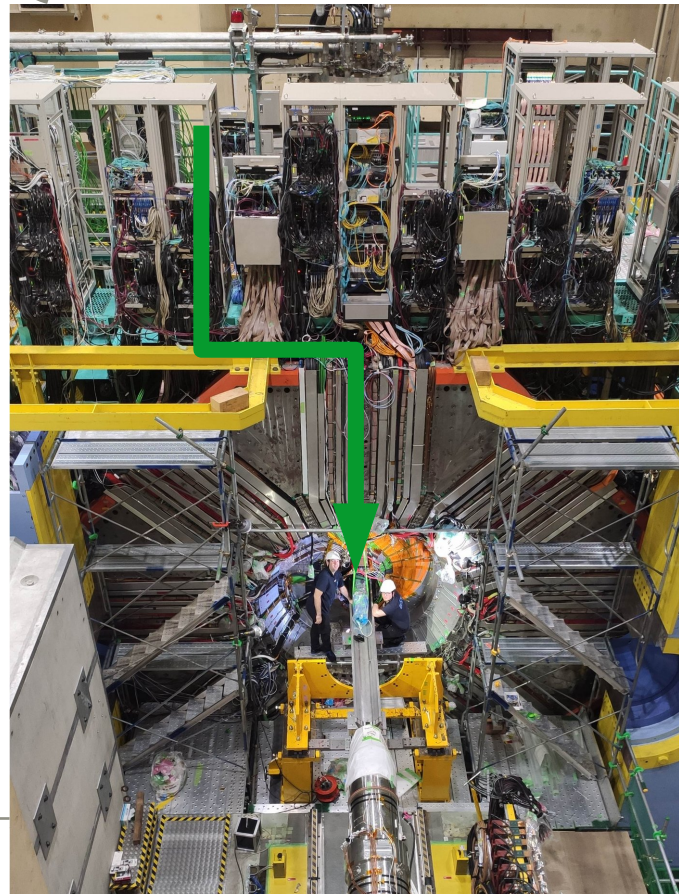
- AC/DC conversion
- NetV → 24V LV
(Commercial component)

- DC/DC conversion for secondary voltages
- Electrical isolation

- Linear post regulation
- Readback of volt. & current
- Limiting of volt. & current

PXD POWERSUPPLY REQUIREMENTS

- Need 23 voltages, ranging from -80V to $+20\text{V}$ with additional dependencies
- Currents up to 3A
- Enabling of hardware current limits
- Supplied via 15m long cables from top of Belle II
 - Compensate for voltage drop
 - 4-wire sensing and stable regulation
- No commercial solution fulfilled all necessary features



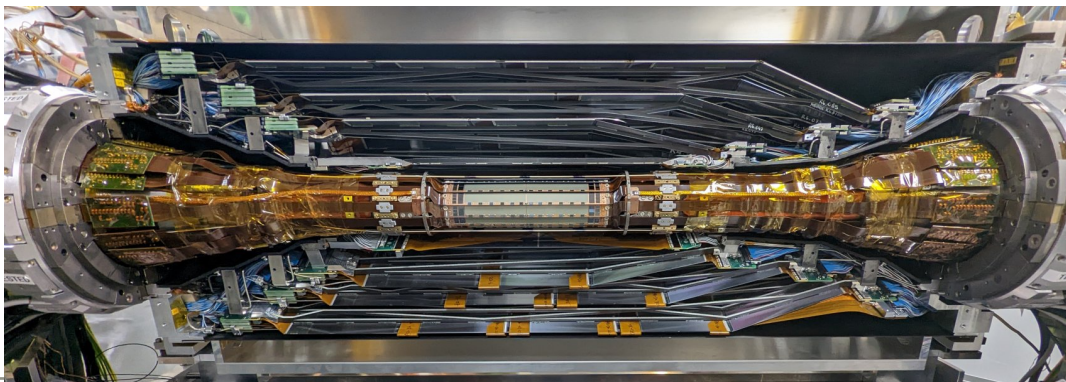
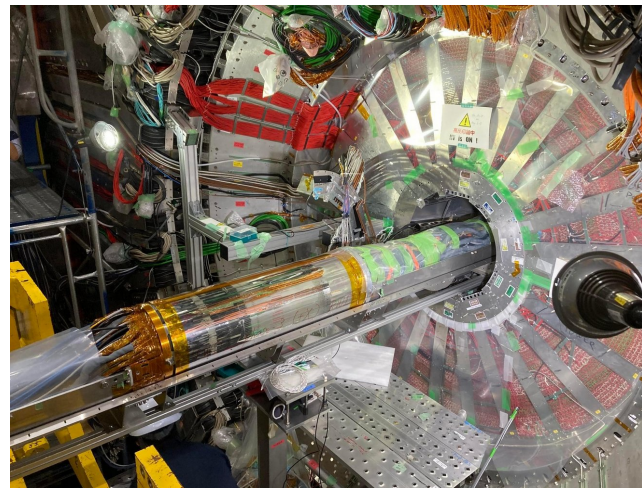
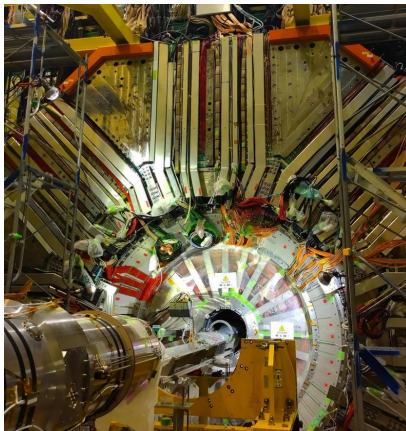
COMMISSIONING OF THE NEW VERTEX DETECTOR (VXD)

PXD1 EXTRACTION

- Old VXD extracted from Belle II in May 23
- Strip Vertex Detector (SVD) reused in new VXD
- PXD1 mechanical inspection did not show visible damage after 4 years operation

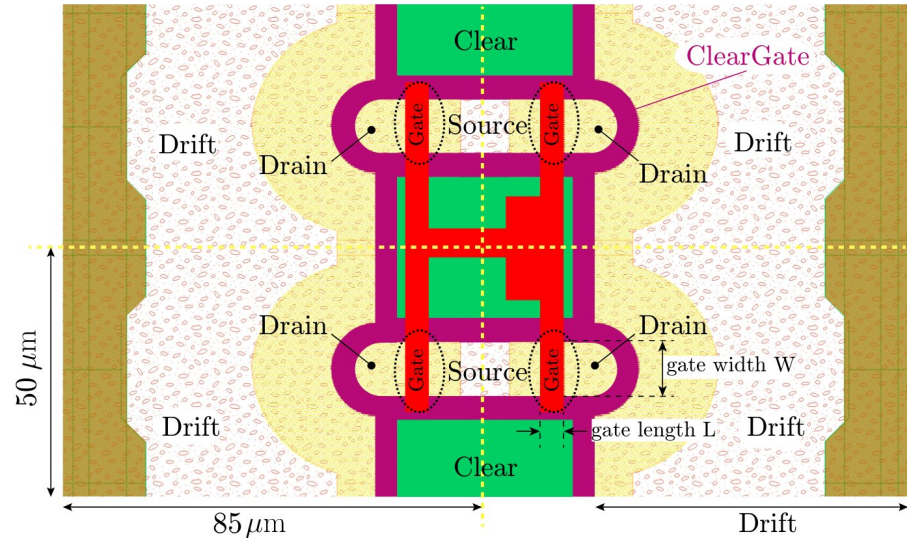
NEW VXD

- Extracted SVD halves installed around PXD2
- Combined standalone testing
- Inserted back in August 2023



DEPFET PIXEL DESIGN

- Four-fold pixel design
 - Allows parallelization in metal routing
 - Source and Clear implant shared among multiple pixels
- Rolling shutter readout mode with four active matrix rows at once → low power
 - 50 kHz → 20 μ s integration time (2x beam rev. cycle)
 - dead-time free except for 100 ns read-clear cycle

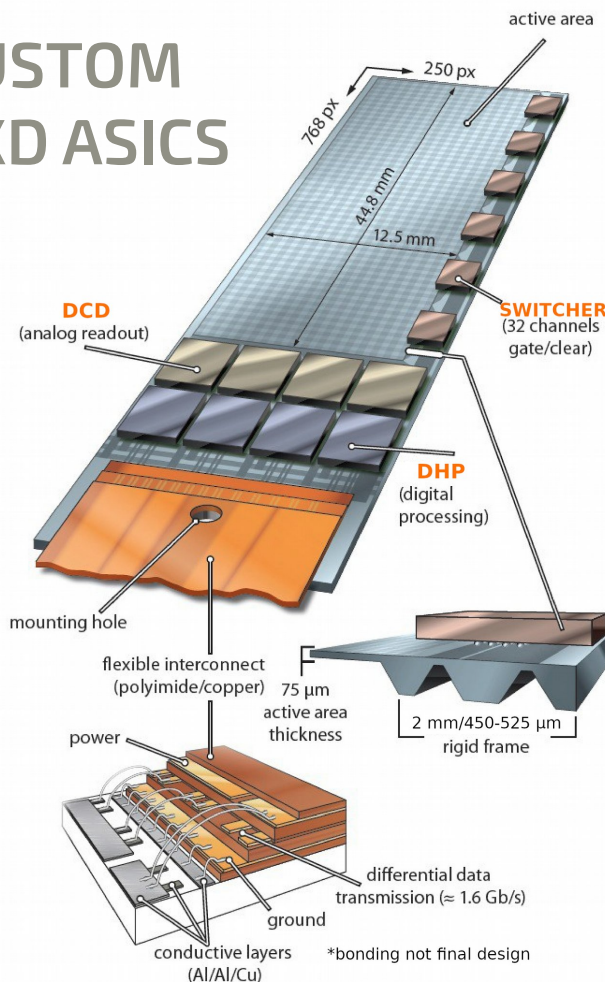
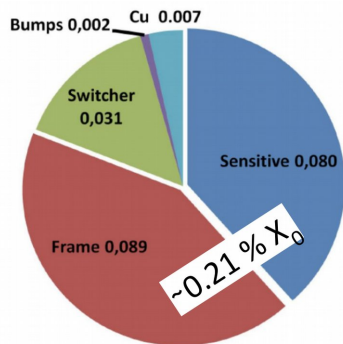


CUSTOM PXD ASICS

DCD

DRAIN CURRENT DIGITIZER

- pipeline 8-bit ADC per channel
- 256 input channels
- 92 ns sampling time
- UMC 180nm
- rad. hard proved (10 Mrad)



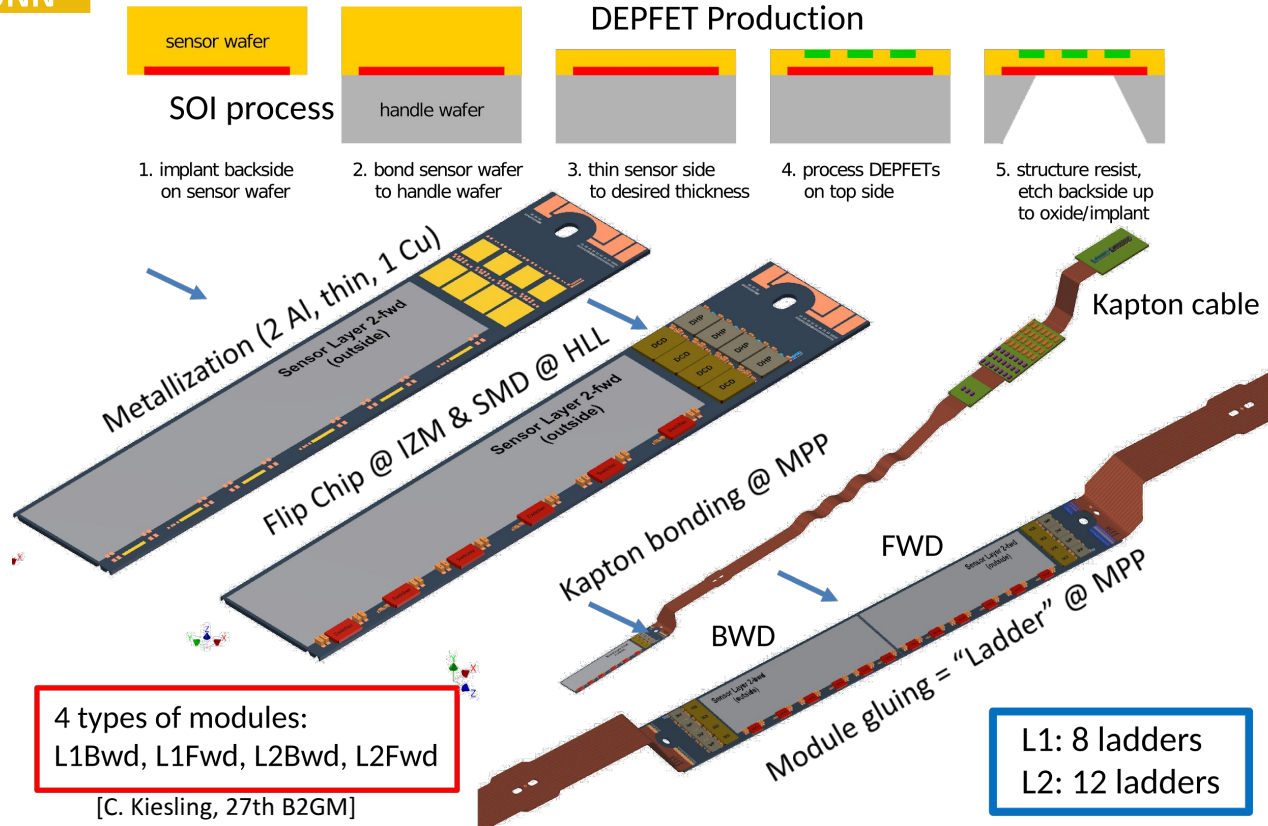
SWITCHER

- gate and clear signals for row control
 - 32 channels control 4 rows each
- fast HV ramping for clear
- AMS/IBM HV CMOS 180nm
- size 3.6 x 1.5 mm²
- rad. hard proved (36 Mrad)

DHP

DATA HANDLING PROCESSOR

- data processing and transmission
 - pedestal correction
 - data reduction (zero suppression)
 - transmission at 1.6 Gbit/s
- TSMC 65nm
- size 4.0 x 3.2 mm²
- rad. hard proved (100 Mrad)

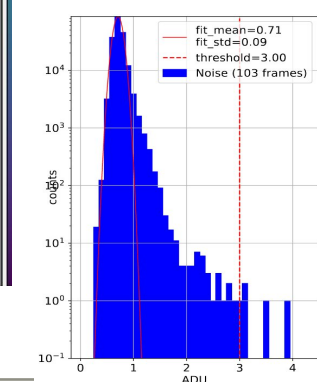
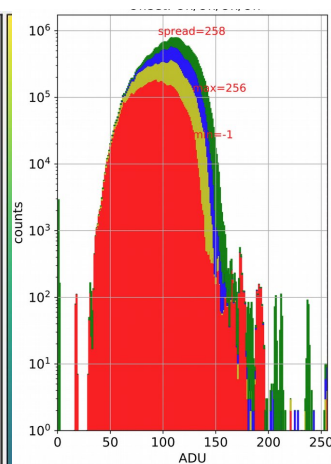
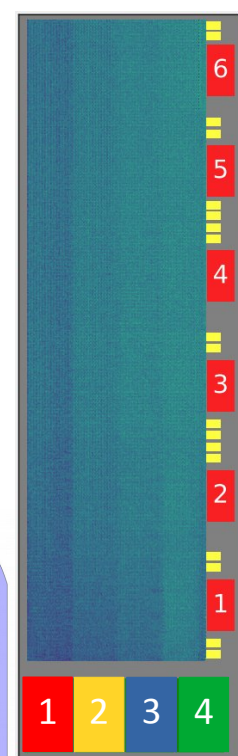
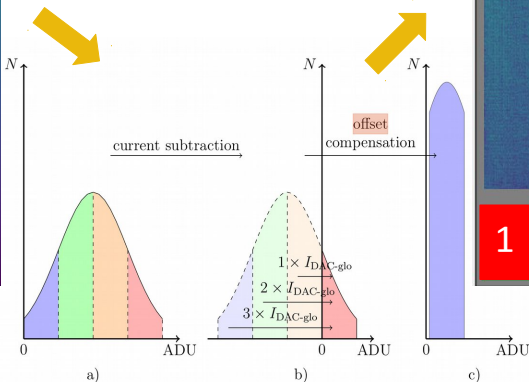
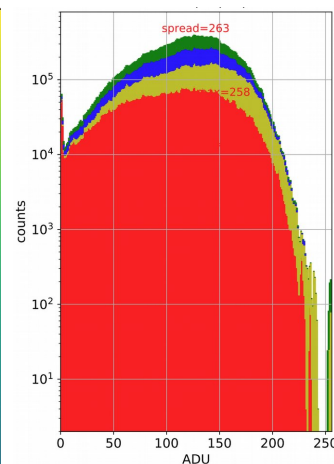
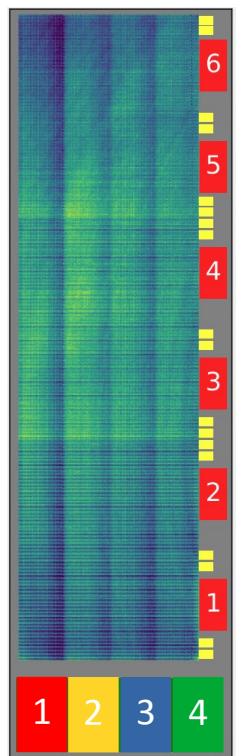


PXD CALIBRATION

BEFORE

AFTER

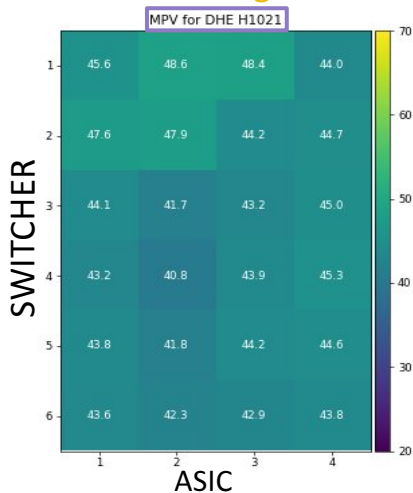
- Characterized modules before installation
- Further optimization during operation
- Improved/automated operation, monitoring and calibration procedures
- DCD calibration
- Biasing optimization
- Pedestal optimization on DCD
 - Pedestal compression via 2-bit DAC
 - Analog Common Mode Correction (ACMC) for noise reduction
 - Low noise $< 1 \text{ ADU} \approx 200 \text{ ENC}$
- Stress tests
 - Power cycling
 - Thermal cycling



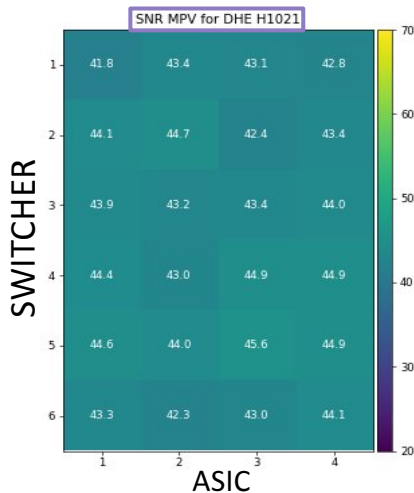
PXD1 PERFORMANCE

- Homogeneous noise and signal response across the module matrix
- Stable throughout 2019-2022
- Slight increase in noise with DCD irradiation
 - Maybe more extensive DCD calibration is needed
 - Under investigation

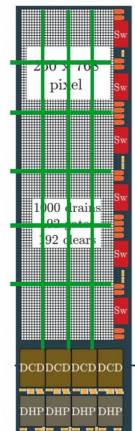
cluster charge MPV



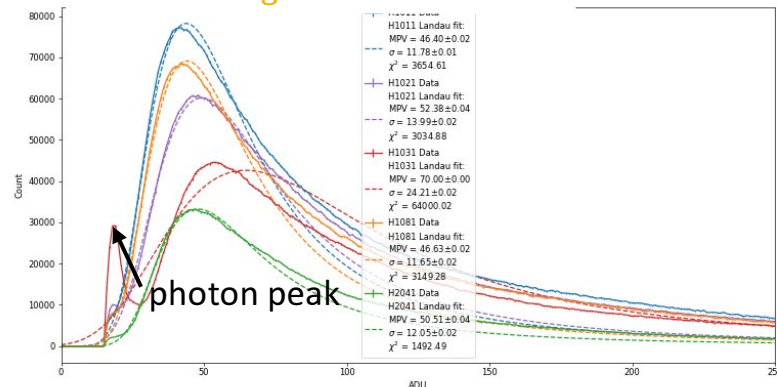
SNR MPV



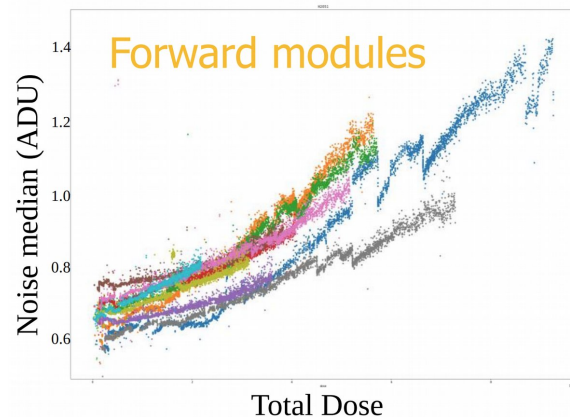
half ladder



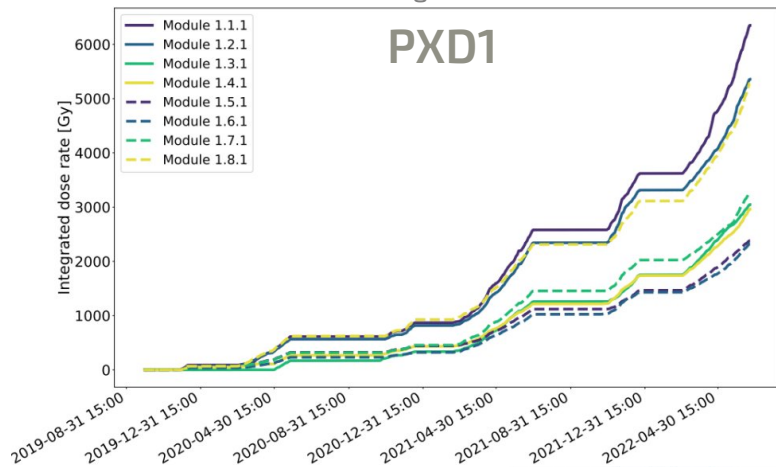
cluster charge distribution



multi pixel cluster ADU



PXD1



- Dose estimation on module occupancy
- Module dependent TID
→ 2.5-6.5 kGy (2019-2022)
- Expected Lifetime exposure of PXD is ~200kGy in 10years

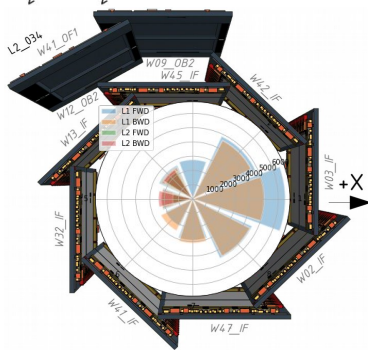


Figure 10 consists of a main plot and an inset plot. The main plot shows the DEPFT Gate Threshold Shift [mV] on the y-axis (ranging from 0 to 10000) versus TID [kGy] on the x-axis (ranging from 3 to 183). The data shows a sigmoidal increase in threshold shift, starting around 1800 mV at 3 kGy and reaching a plateau of approximately 9000 mV for TID values above 93 kGy. The inset plot zooms in on the low TID region, with the x-axis ranging from 0.125 to 183 kGy and the y-axis ranging from 0 to 6000 mV. It shows the initial rapid increase in threshold shift, starting from near 0 mV at 0.125 kGy and reaching about 5000 mV at 183 kGy. Both plots include data points with error bars representing the 5% to 95% range, and a blue shaded area representing the interquartile range (25% to 75%). A red line indicates the median shift.

$$MPV \sim g_q \sim \sqrt{I_{DS}} \sim (V_{GS} - V_{th})$$

- Oxide damage $\rightarrow$ shift of MOSFET threshold V_{th}
- Compensated by regular adjustment of V_{GS}
 $\rightarrow$ keep g_q constant
- Lab results consistent with PXD experience

TRAPPED OXIDE CHARGES

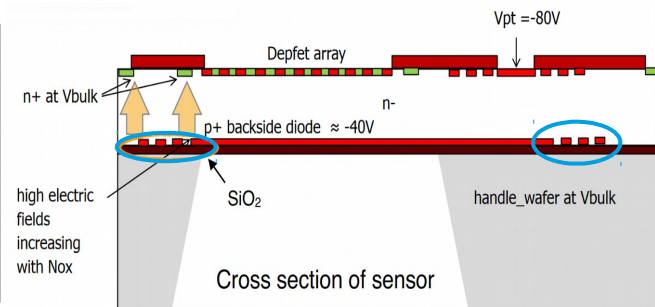
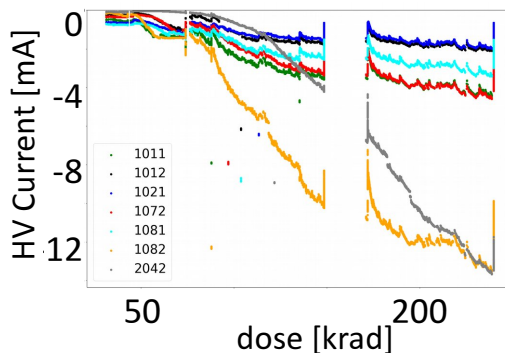
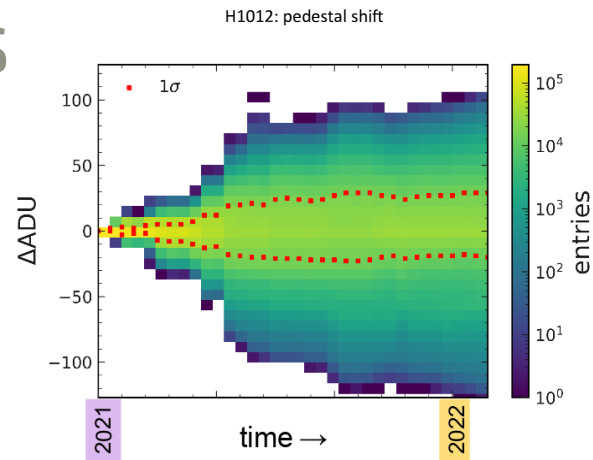
- Shift of DEPFET threshold voltage

PEDESTAL AGING

- Broadening of pedestal distribution and noise increase
- Inhomogeneous across matrix
→ potential challenge for pedestal compression

INCREASING HV CURRENT

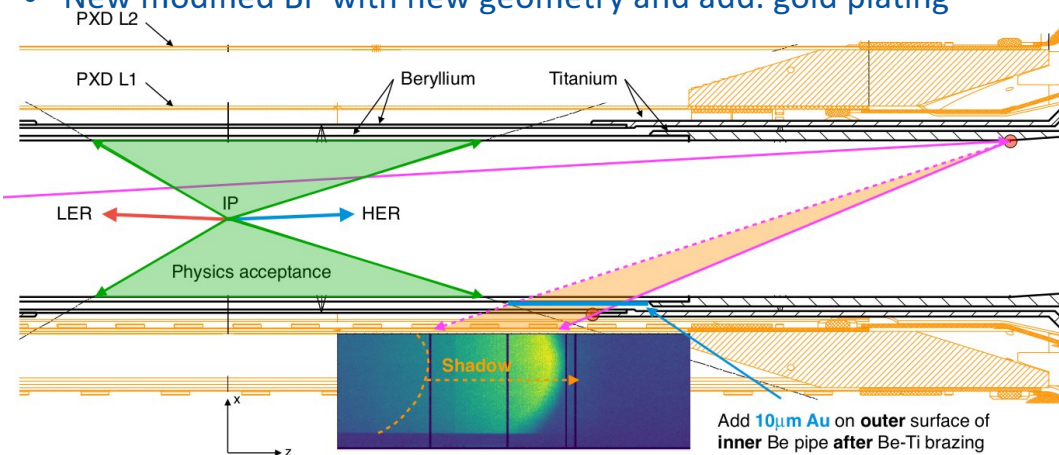
- Guard rings are (partially) shorted
- Buried oxide damage → high E-fields
→ avalanche current multipl. → High I_{HV}
- Modification of PS units
→ Performance not affected



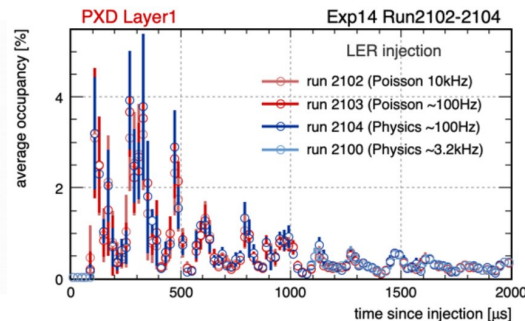
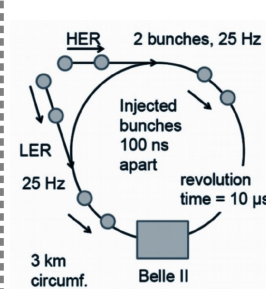
BACKGROUND CHALLENGES

SYNCHROTRON RAD. BACKGROUND

- From back-scattered SR fan photons on edge of Ti BP
- Appear during HER injections (large betatron osc. during cooldown)
 - inhomogeneous module irradiation
 - deterioration of clustering and tracking
- New modified BP with new geometry and add. gold plating



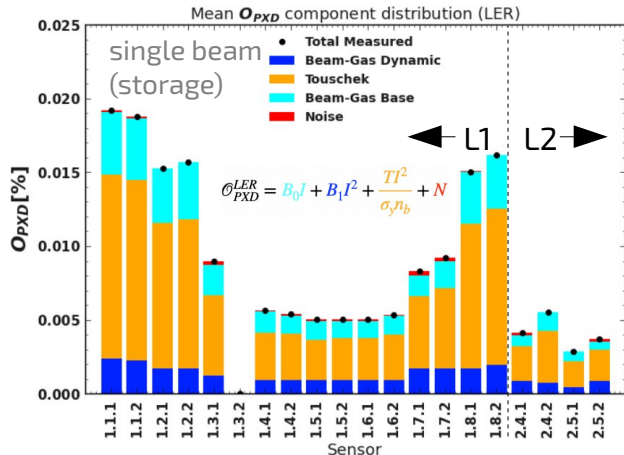
INJECTION BACKGROUND



- From newly injected bunches (50Hz)
- Touschek effect limits beam lifetime to few mins → continuous injection
- 3% occupancy threshold in PXD
 - no problem so far
- Damping takes ~ms
 - Full and gated vetoes

BEAM STORAGE

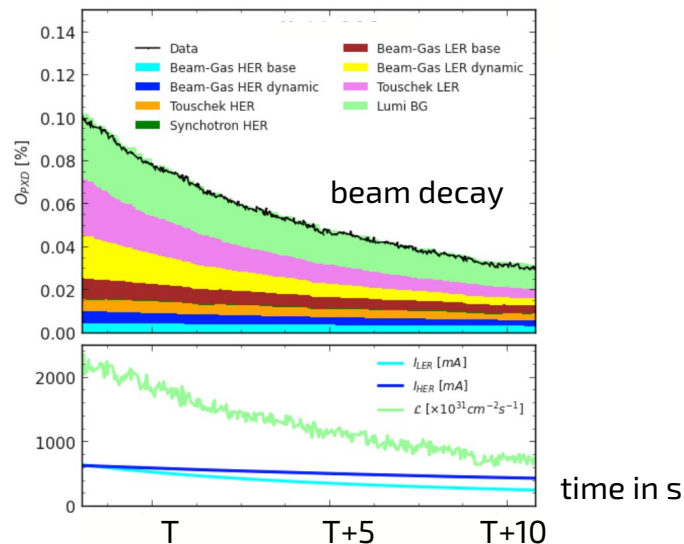
- **Beam-gas scattering**
beam interaction with residual gas molecules
- **Touschek scattering**
Coulomb scattering within bunch



LUMINOSITY (BEAM COLLISIONS AT IP)

- **Two-photon interaction**
- **Radiative Bhabha**

beam collision (storage + lumi)

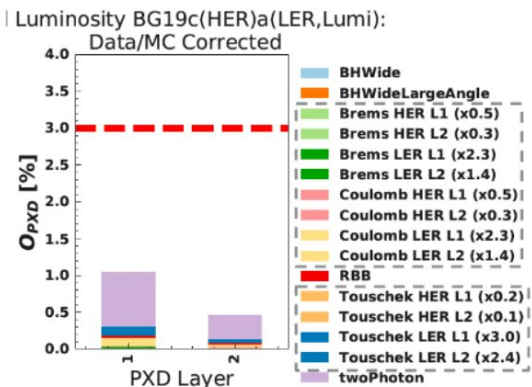


BEAM BACKGROUND EXTRAPOLATION

BASED ON SINGLE BEAM DATA/MC @ DEC 20 2021

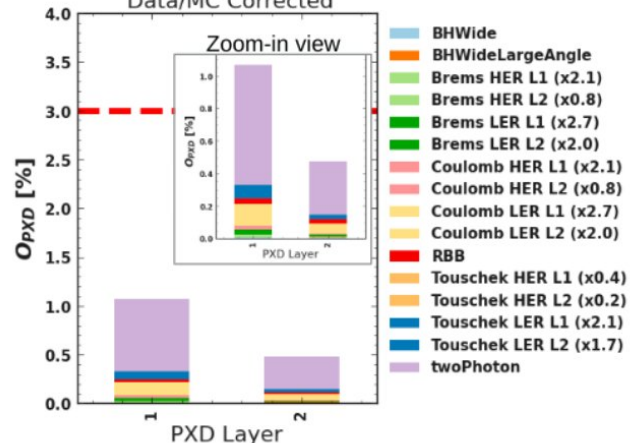
Parameters @ Original Design Optics	LER	HER
Beam current [A]	3.6	2.6
N. of bunches	2500	2500
Vertical beam size [μm]	24	10
β_x^*/β_y^* at IP [mm]	32/0.27	25/0.30
Pressure [nTorr]	1	1

- Updated LER & HER components using current Data/MC factors
- Small changes expected for total extrapolation
→ dominated by two-photon background



Use data/MC 27.06.2020 bugfix2 ratios to correct the BG19c sample
[taken from Sally's talk @ PXD Background Workshop, 17.08.2021]

Full Luminosity BG19c(HER)a(LER,Lumi):
Data/MC Corrected



PXD Backgrounds @ Belle II

Single-beam backgrounds:

▶ **Touschek scattering** → scattering of particles within a bunch →
Touschek rate $\propto N_{\text{particles}} \times \rho \rightarrow I \times \frac{I}{\sigma_y n_b}$

▶ **beam-gas scattering** → Coulomb scattering and Bremsstrahlung (scattering off gas molecules) → **Beam-gas rate** $\propto N_{\text{gas molecules}} \times N_{\text{particles}} \rightarrow P \times I \times Z_{\text{eff}}^2$

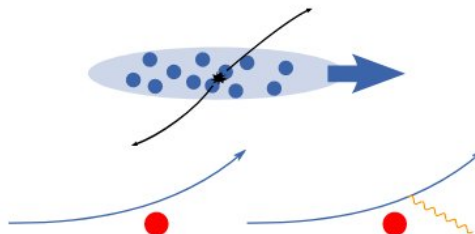
▶ **synchrotron radiation background** → consequence of a radial acceleration of the beam's particles achieved in bending magnets and quadrupoles

▶ **injection background** → continuous injection of charge into beam bunch modifying the beam bunch

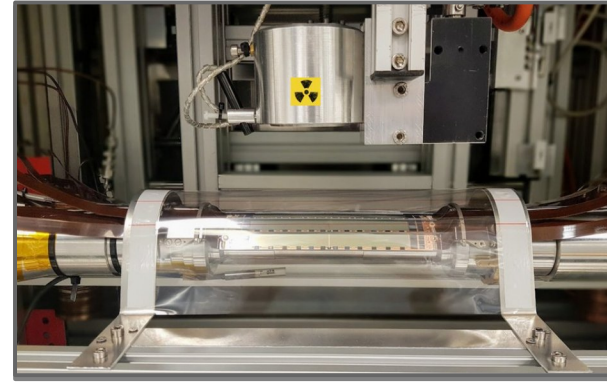
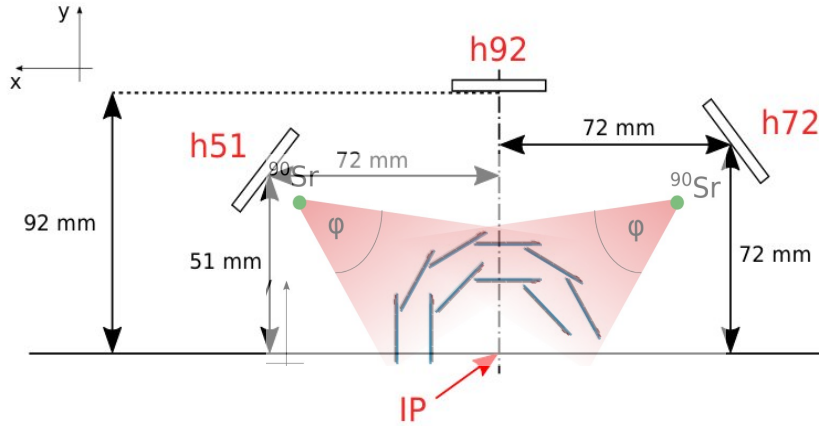
Single-beam backgrounds can be mitigated with beam-steering, collimators, and vacuum-scrubbing

Luminosity backgrounds:

▶ **two-photon background** → leading luminosity background ($e^+e^- \rightarrow e^+e^-\gamma\gamma \rightarrow e^+e^-e^+e^-$), unlike any of the backgrounds above cannot be reduced!

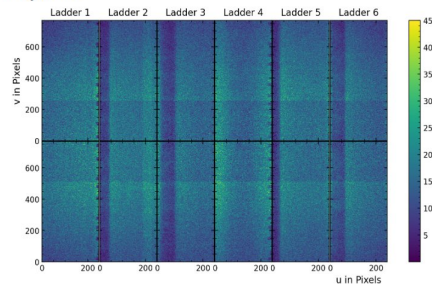


PXD2 BIAS OPTIMIZATION

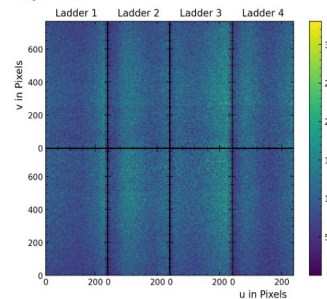


More than 200 voltage combinations, 15 minutes each

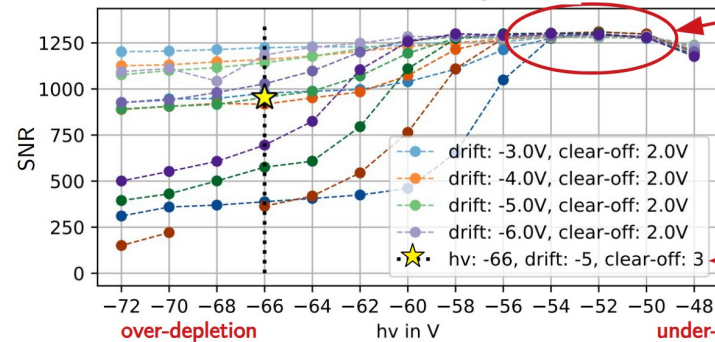
Layer 2:



Layer 1:



H1021 cluster charge fit



Better Parameters
Half-Shell Scan

Best Parameters
Mass-Testing

PXD2 MODULE STATUS

GENERAL

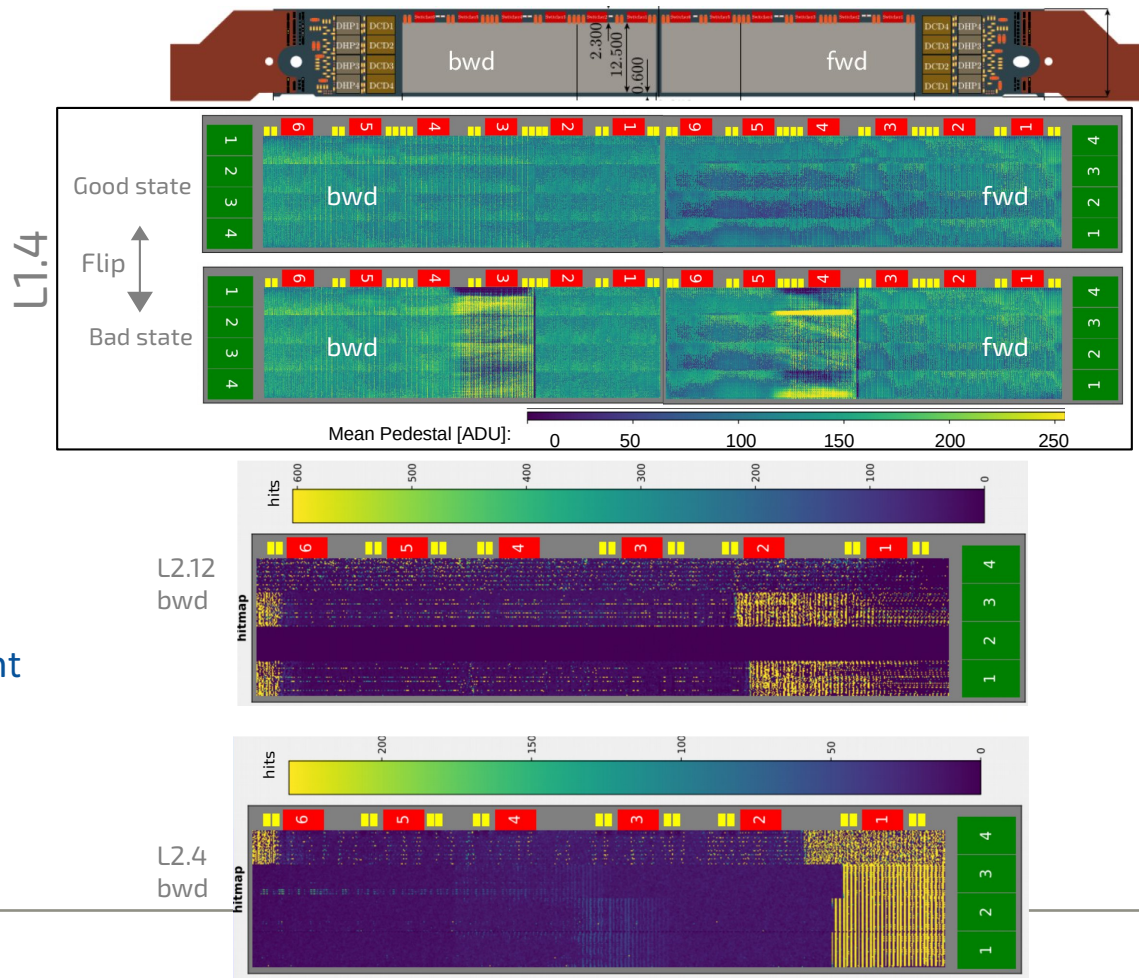
- All 40 modules operable

UNSTABLE SWITCHERS L1.4

- Two module states
- Problematic readout channel or broken switcher?
- Temporary solution: reduction of gate-on voltage

PEDESTAL GLITCHES

- 2 modules with regions of significant pedestal shifts within individual frames
- Dominant structures in L2.4bwd, L2.12bwd → mask these pixels

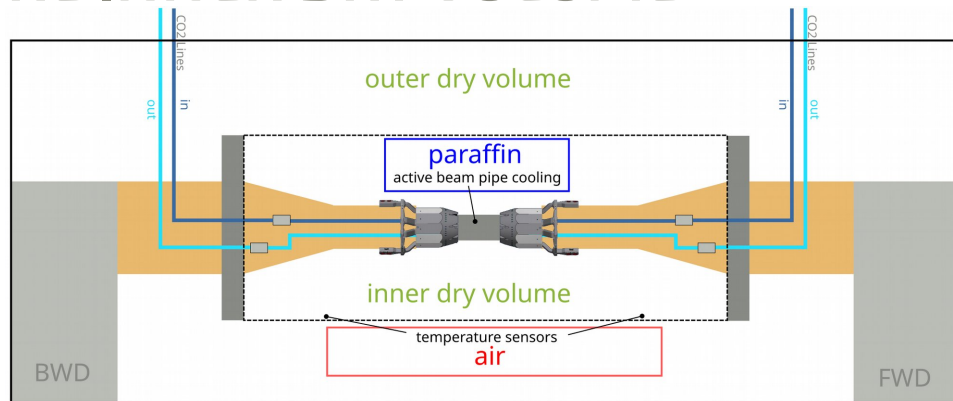


AIRTEMPERATURE INNER DRY VOLUME

PXD1 COOLING PARAMETERS

- Inner dry volume exceeded 30 °C
- No saturation observed → stopped
- Elevated temperatures and mechanical stress can be problematic for ladder glue joint

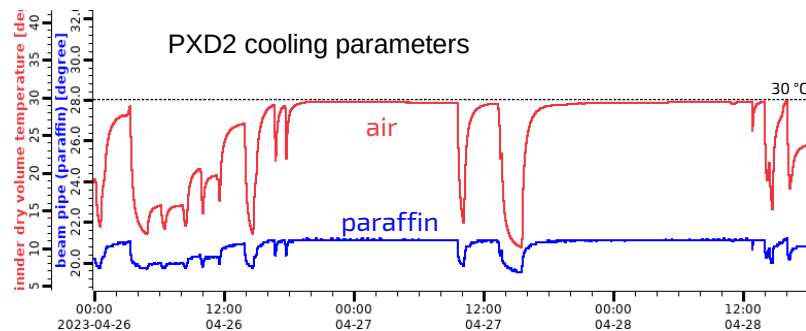
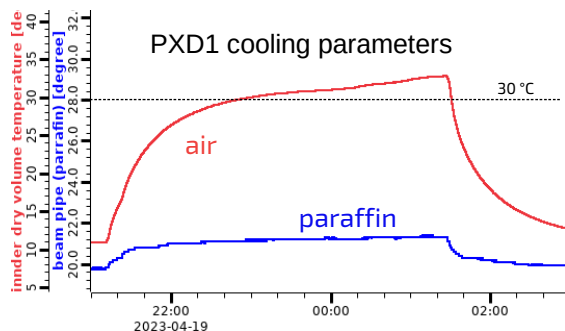
CO2 : -20°C
N2 : 28l/min



PXD2 COOLING PARAMETERS

- ~20h permanent operation
- Air temp. saturated at 29 °C
- Paraffin (beam pipe) temp. stable at 21 °C

CO2 : -25°C
N2 : 32l/min



BEAM LOSS EVENTS

CAUSE

- Vacuum leak sealant “VACSEAL” found to be strong candidate for causing SBL events

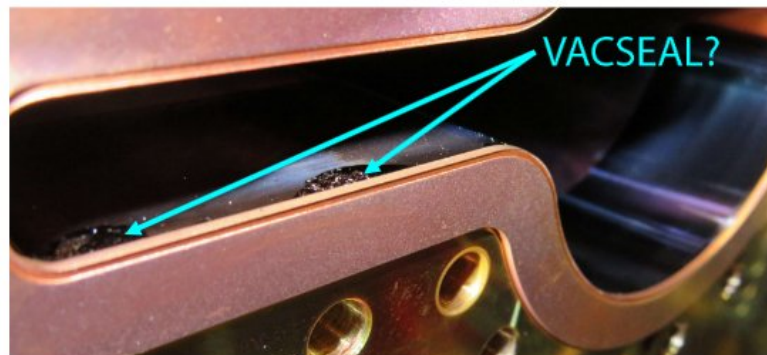
IMPACT OF VACSEAL REMOVAL

- One bellows chamber exchanged on 6th Nov. 2024
- Before (Oct 9th – Nov 6th) : 0.141 SBL / beam dose(1/Ah)
- After (Nov 6th – Dec 27th) : 0.043 SBL / beam dose (1/Ah)
- No SBLs with pressure burst in this section after replacement

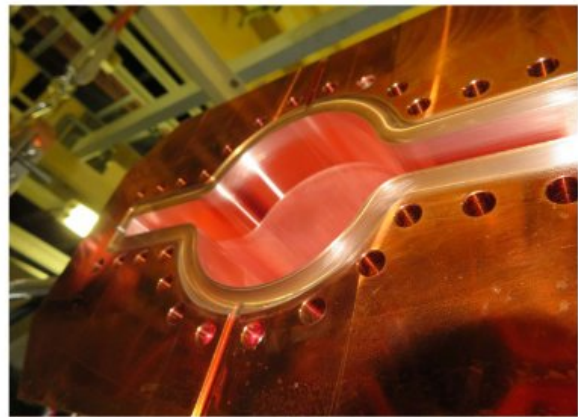
OUTLOOK

- Cleaning and VACSEAL removal in pipes and bellows scheduled for 2025 shutdown

Before removal



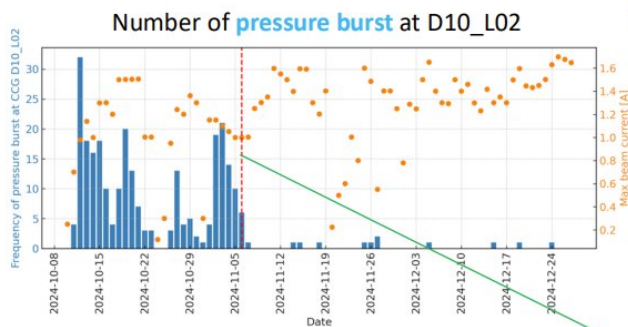
After removal



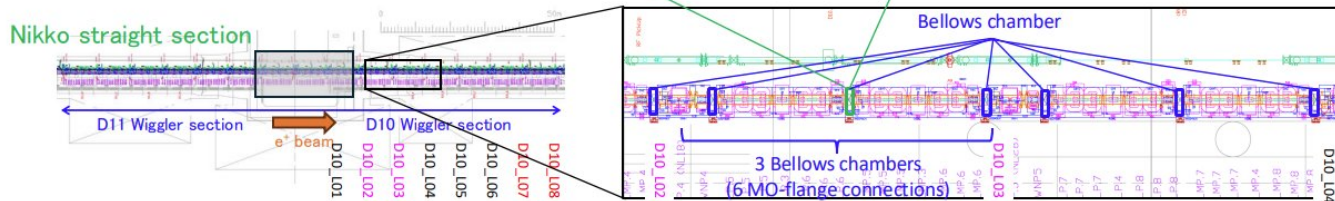
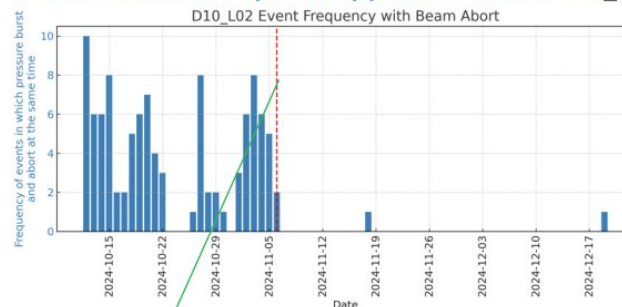
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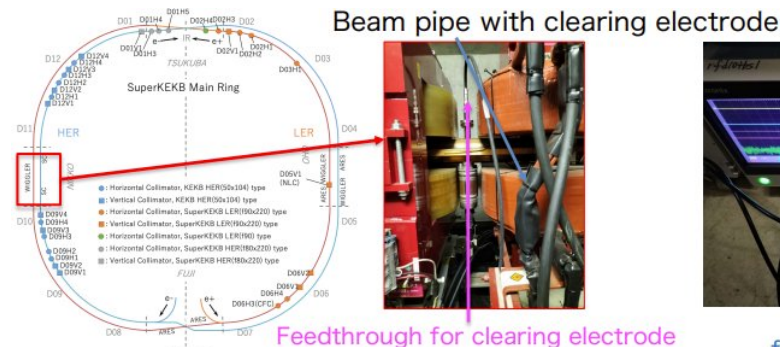
Number of beam abort accompanied by pressure burst at D10_L02



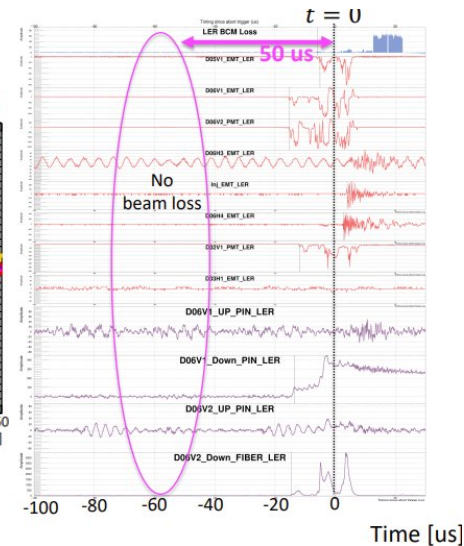
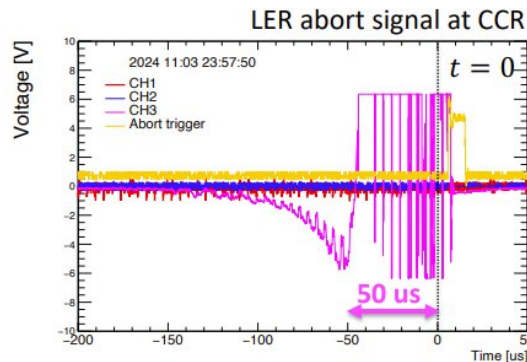
BEAM LOSS EARLY DETECTION

ONGOING DEVELOPMENT

- New sensors, improved signal transmission
→ Faster and earlier detection of SBLs
- Plan : Include signals into PXD interlock
→ Lower threshold to put PXD into safe OFF state
- Candidate : Signal in clearing electrode
 - Signal detected close to area where pressure burst occurred
 - Strong correlation with SBLs
- Cable routing started (amplification and integration still TBD)
- To benefit from faster detection, we must minimize PXD shutdown delay

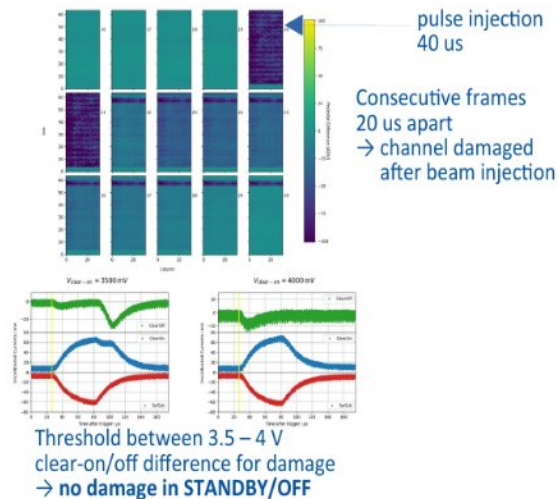
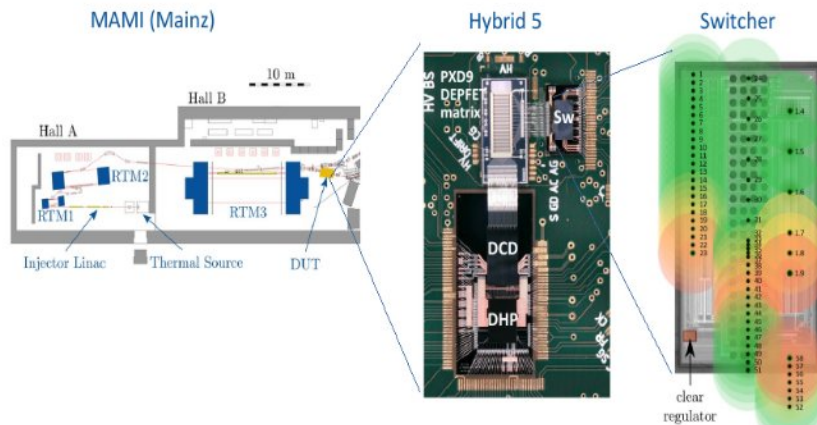
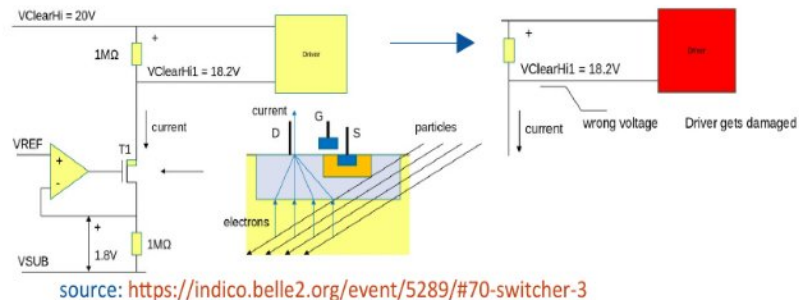


Monitor the signal from the feedthrough



SWITCHER DAMAGE MECHANISM

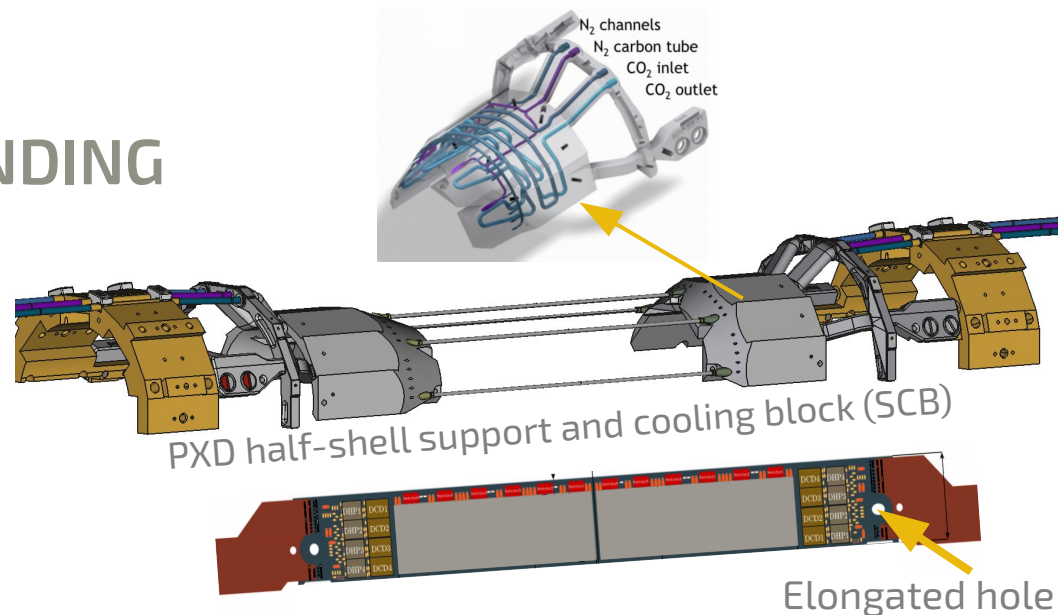
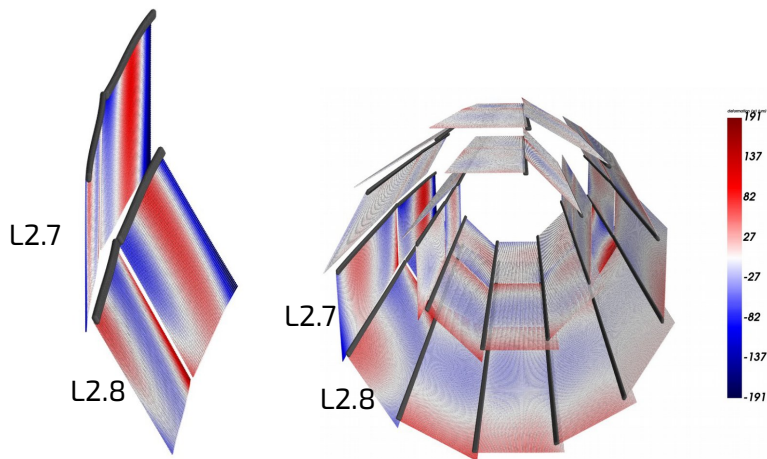
- Reproduced in laboratory with electron pencil beam:
“Irradiation Burst Studies on Belle II PXD Module Components”
<https://docs.belle2.org/record/3258>
- Regulator structure susceptible
 - Transient current causes overvoltage
→ damages driver
- Not understood: damage in individual channels



LADDER BENDING

COOLING PROPERTIES

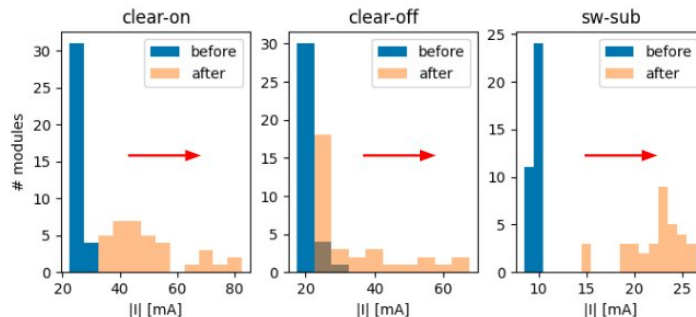
- Power consumption $\sim 9\text{W}$ per module
→ 360 W for full detector
- 2-phase CO_2 for DHP/DCD (8W)
- N_2 gas for sensor + switchers (1W)



- Thermal stress should be prevented by ladder gliding
- Problem of unsatisfactory gliding known from commissioning
- Dedicated bending study: ladder & glue joint still intact even after 90k cycles with sagitta $\geq 1\text{mm}$ (up to 2mm)
- **BUT** : If L2.7 turned off, could potentially touch L2.8
→ Implementation of interlock condition to prevent this condition

OPERATION TEMPERATURE

- After damage on Switchers, currents are increased
→ Increased temperatures esp. at balcony
- Restrain temperature increase by turning off additional modules

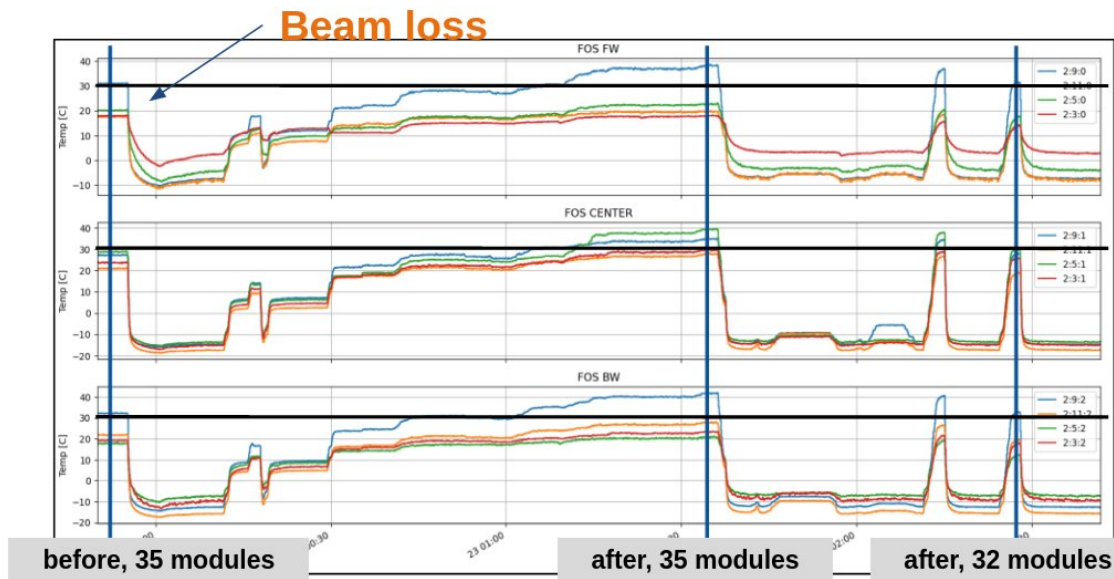


DESY TESTS

- Glue joint may open under mechanical stress & high temperature
- Glue softens at $\sim 48^\circ\text{C}$
- Ladder gets kinked at joint, but intact
- In all tests modules stayed connected

SAFETY MECHANISMS

- Alarm limits on 33°C and 35°C FOS tem
- Emergency off at 45°C



PXD Bowing

Study bending of ladders

- Different temperatures and expansion coefficients introduce mechanical stress on ladders
- Non optimal gliding mechanisms can not absorb the full effect
-> Ladder start to bend
- Investigate if and how bending depends on beam operation
- Study bowing with variable which is sensitive to bowing:

$$\text{Res } v = \text{hit} - \text{intercept}$$

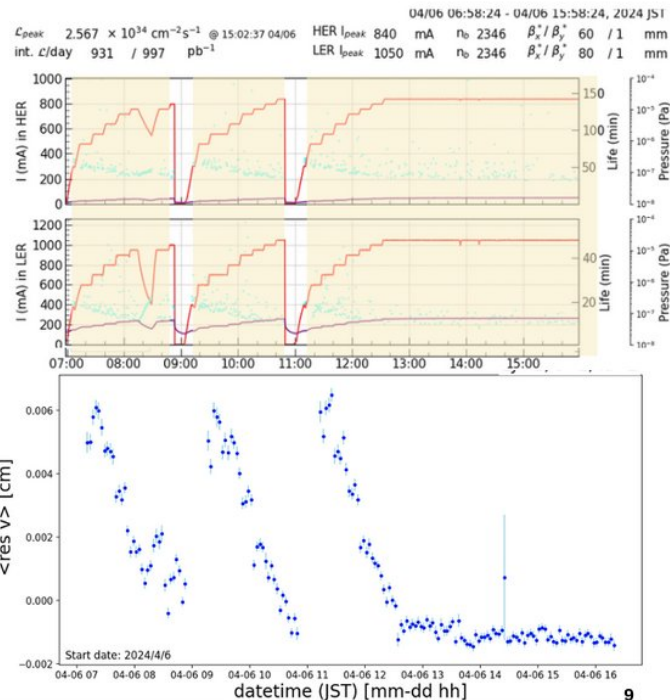
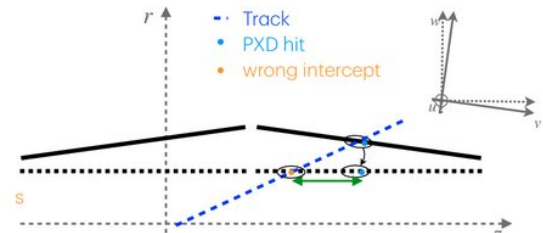
Track w. PXD hits Refitted track w/o PXD hits

Observation:

- Bending depends on local sensor temperature and beam current (hot spot)
- Increasing current = decreasing residual (and vice versa)
- Underlying concept not fully understood
-> Bending behaviour could change with even higher beam currents

Plans:

- Ongoing work to include variable in DQM module (on-time tracking of bending)
- Implementation before next run start



LADDER BENDING STUDIES AT DESY

Thermal dummy L2 ladder bent with gradually increasing sagitta

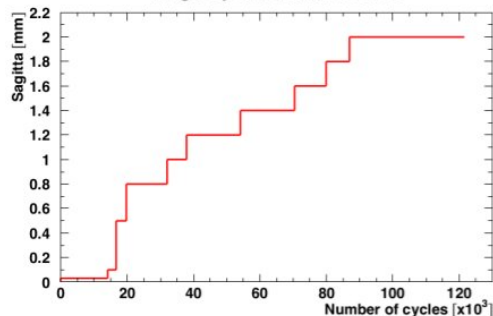
- ~ 4500 cycles at $\Delta 0.9$ mm
- ~ 2500 cycles at $\Delta 1.1$ mm
- >100 cycles at 1.8 mm
 $\rightarrow$ ladder developed two kinks

$\rightarrow$ Thermal dummy ladder mechanically different

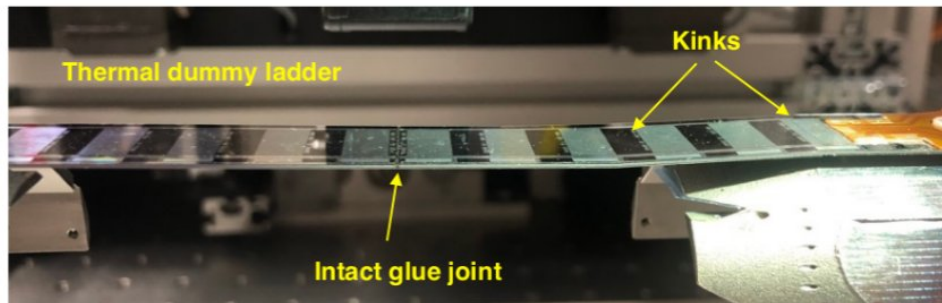
$\rightarrow$ Both kinks at resistor lines

Repeat with recently glued L2 dummy ladder

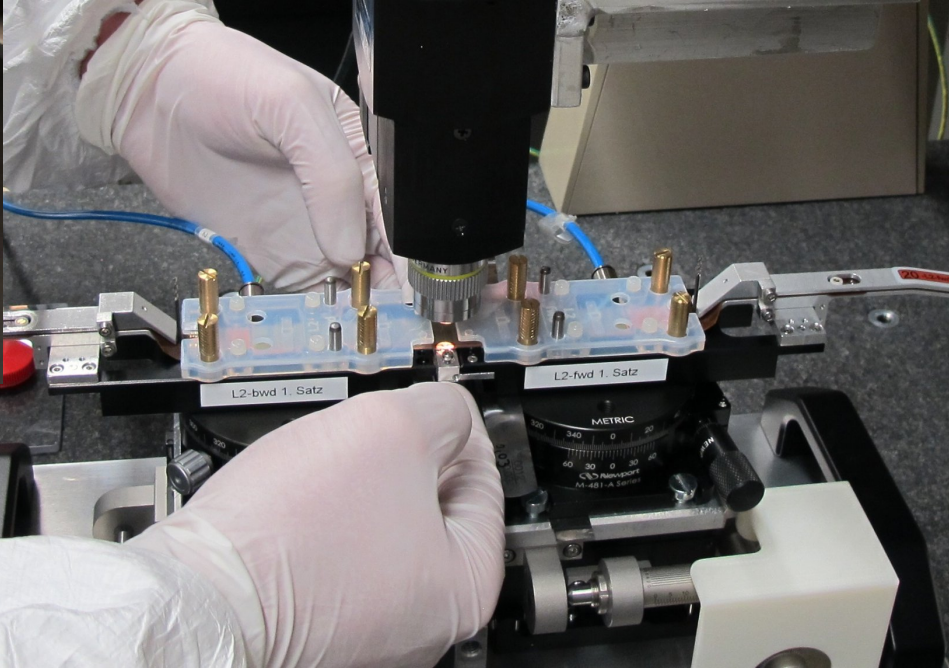
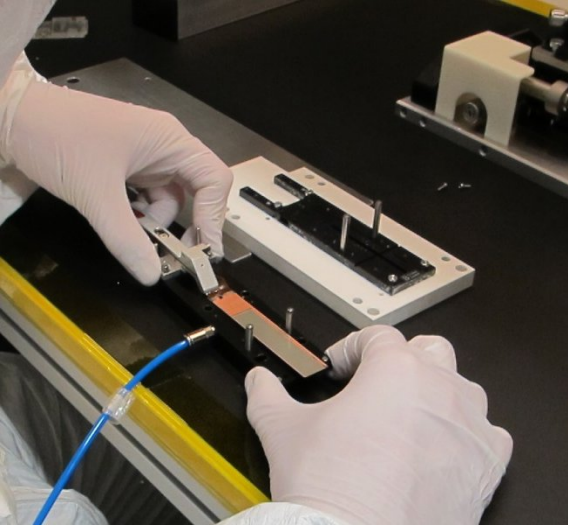
L2 glue joint endurance test



After more than two months with more than 90k cycles with sagitta >1 mm $\rightarrow$ Ladder still intact



HANDLING, LADDER ALIGNMENT & GLUING



Tracking at SuperKEKB

Challenges

- **increased backgrounds** with instantaneous lumi
 - beam lifetime only few minutes
⇒ continuous “top up” injection (for 2400 bunches)
(50 Hz @ 4 ms cooldown ⇒ 4 ms damping time with particle losses)
 - “Synchrotron”, “Touschek intra-bunch scattering”, “Bhabha”, “2 photon”...
 - challenge for detector/tracking overall
(challenges for PXD discussed explicitly later)
- **smaller Lorentz boost** (for better beam lifetime at 4 GeV > 3.5 GeV)
 - critical for time dependent measurements

Track reconstruction and PXD role

- (HLT) **track finding seeded in CDC** ($p_T > 100$ MeV) or else **SVD**
- **PXD hits** used in offline track fit → **improved vertex resolution**
- Regions of Interest (**ROI**) filtering:
 - HLT: extrapolates tracks to ROIs on PXD for readout to reduce data rate
not needed yet
- PXD layer one crucial for *impact parameter resolution*
- PXD layer two (will be) important to retain performance at *higher backgrounds*

